Intel® Desktop Board CA810E
Technical Product Specification

October 1999

Order Number A03415-001

The Intel® CA810E board may contain design defects or errors known as errata that may cause the product to deviate from published specifications. Current characterized errata are documented in the CA810E Monthly Specification Update.

Revision History

Revision	Revision History	Date
-001	Final draft of the Desktop Board CA810E Technical Product Specification.	October 1999

This product specification applies only to standard CA810E board with BIOS identifier CA81020A.86A.

Changes to this specification will be published in the CA810E Monthly Specification Update before being incorporated into a revision of this document.

Preface

This Technical Product Specification (TPS) specifies the board layout, components, connectors, power and environmental requirements, and BIOS for the Intel® CA810E desktop board. It describes the standard board product and available manufacturing options.

Intended Audience

The TPS is intended to provide detailed, technical information about the board and its components to the vendors, system integrators, and other engineers and technicians who need this level of information. It is specifically *not* intended for general audiences.

What This Document Contains

Chapter	Description
1	A description of the hardware used on this board
2	A map of the resources of the board
3	The features supported by the BIOS Setup program
4	The contents of the BIOS Setup program's menus and submenus
5	A description of the BIOS error messages, beep codes, and Power On Self Test (POST) codes

Typographical Conventions

This section contains information about the conventions used in this specification. Not all of these symbols and abbreviations appear in all specifications of this type.

Notes, Cautions, and Warnings

NOTE

Notes call attention to important information.

CAUTION

Cautions are included to help you avoid damaging hardware or losing data.

WARNING

Warnings indicate conditions that, if not observed, can cause personal injury.

Other Common Notation

‡	Indicates a feature that is implemented—at least in part—on a riser card.
#	Used after a signal name to identify an active-low signal (such as USBP0#).
(NxnX)	When used in the description of a component, N indicates component type, xn are the relative coordinates of its location on the board, and X is the instance of the particular part at that general location. For example, J5J1 is a connector, located at 5J. It is the first connector in the 5J area.
KB	Kilobyte (1024 bytes)
Kbit	Kilobit (1024 bits)
MB	Megabyte (1,048,576 bytes)
Mbit	Megabit (1,048,576 bits)
GB	Gigabyte (1,073,741,824 bytes)
xxh	An address or data value ending with a lowercase h indicates a hexadecimal value.
x.x V	Volts. Voltages are DC unless otherwise specified.
†	This symbol is used to indicate third-party brands and names that are the property of their respective owners.

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4 BIOS Setup Program

5 Error Messages and Beep Codes

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1 Desktop Board Description

What This Chapter Contains

1.1 Overview

1.1.1 Feature Summary

The CA810E desktop board's features are summarized below.

Table 1. Feature Summary

Form Factor	microATX (9.6 inches by 9.6 inches)
Processor	Support for • Intel® Pentium® III processor (with integrated 256 KB level two cache) • Intel® Celeron™ processor (with integrated 128 KB level two cache)
Chipset	The Intel® 810E chipset consisting of: • Intel® 82810E DC-133 Graphics and Memory Controller Hub (GMCH) • Intel® 82801AA I/O Controller Hub (ICH) • Intel® 82802AB Firmware Hub (FWH)
Memory	• Two 168-pin dual inline memory module (DIMM) sockets • Support for up to 512 MB of 100 MHz non-ECC, unbuffered synchronous DRAM (SDRAM) — 32 MB to 256 MB using 16 MB/64 Mbit technology — 512 MB maximum using 128 Mbit technology • Support for serial presence detect (SPD) and non-SPD DIMMs
I/O Control	SMSC LPC47M102 low pin count (LPC) interface super I/O controller
Audio Subsystem	• Creative Sound Blaster† AudioPCI 128V audio solution • Crystal Semiconductor CS4297 AC '97 stereo audio codec
Peripheral Interfaces	• Two serial ports • Two USB ports • One parallel port • PS/2 keyboard • PS/2 mouse
Graphics Subsystem	Intel 82810E DC-133 Graphics and Memory Controller Hub (integrated in the chipset) with 4 MB of 133 MHz video cache memory
Expansion Capabilities	Four PCI bus connectors
BIOS	• Intel/AMI BIOS • Intel 82802AB Firmware Hub (FWH) 4 Mbit flash memory • Support for SMBIOS, Advanced Configuration and Power Management Interface (ACPI), Advanced Power Management (APM), and Plug and Play (see Section 1.3 for specification compliance levels)
Other Features	• Speaker • Fan 1 (chassis) and fan 2 (processor) connectors with fan tachometer

1.1.2 Manufacturing Options

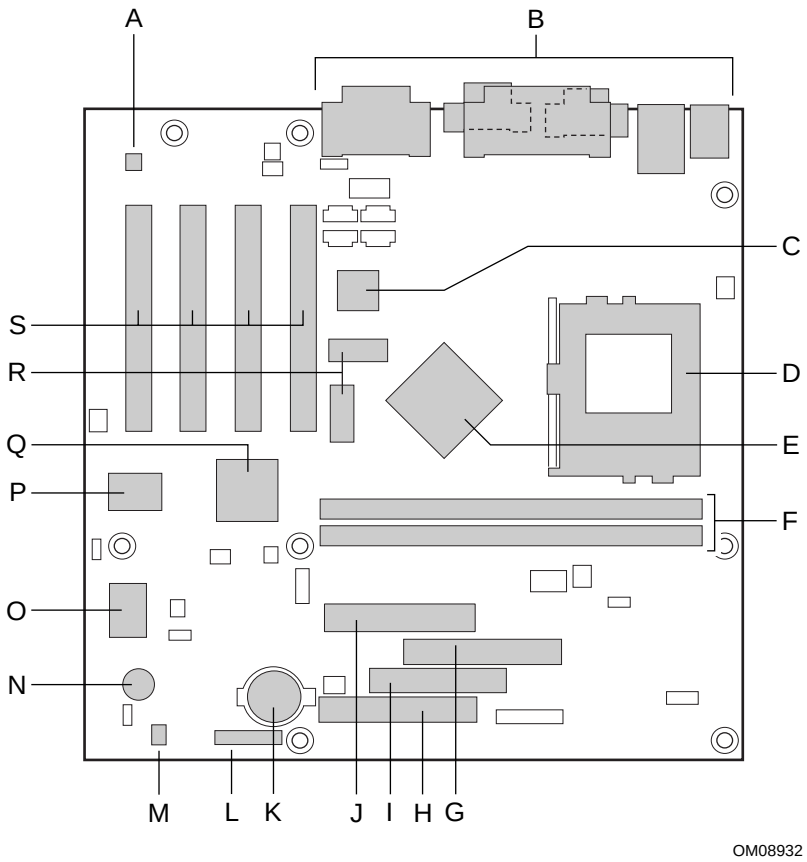
Not all of the following manufacturing options are available in all marketing channels. Please contact your Intel representative to determine what manufacturing options are available to you.

Table 2. Manufacturing Options

Fan connector	Fan 3 without tachometer
Chassis Intrusion	Chassis intrusion detect connector
USB	USB front panel connector
Hardware Monitor Subsystem	• Wired for Management (WfM) compliant • Voltage sensor to detect out of range values
LAN Controller	Intel® 82559 PCI LAN controller with RJ-45 LAN connector
Power Management	Alert on LAN† component

1.1.3 Board Layout

Figure 1 shows the major components of the CA810E desktop board.



A	Crystal Semiconductor CS4297 audio codec	K	Battery
B	Back panel connectors	L	Front panel connector
C	Intel 82559 LAN controller (optional)	M	Intel 82802AB Firmware Hub (FWH)
D	PGA370 processor socket	N	Speaker
E	Intel 82810E DC-133 Graphics and Memory Controller Hub (GMCH)	O	SMSC LPC47M102 super I/O controller
F	DIMM sockets	P	Creative ES1373 digital audio controller
G	Secondary IDE connector	Q	Intel 82801AA I/O Controller Hub (ICH)
H	Primary IDE connector	R	Display cache
I	Diskette drive connector	S	PCI bus connectors
J	Power supply connector		

Figure 1. microATX Board Components

1.1.4 Block Diagram

Figure 2 is a block diagram showing the relationship among the major components.

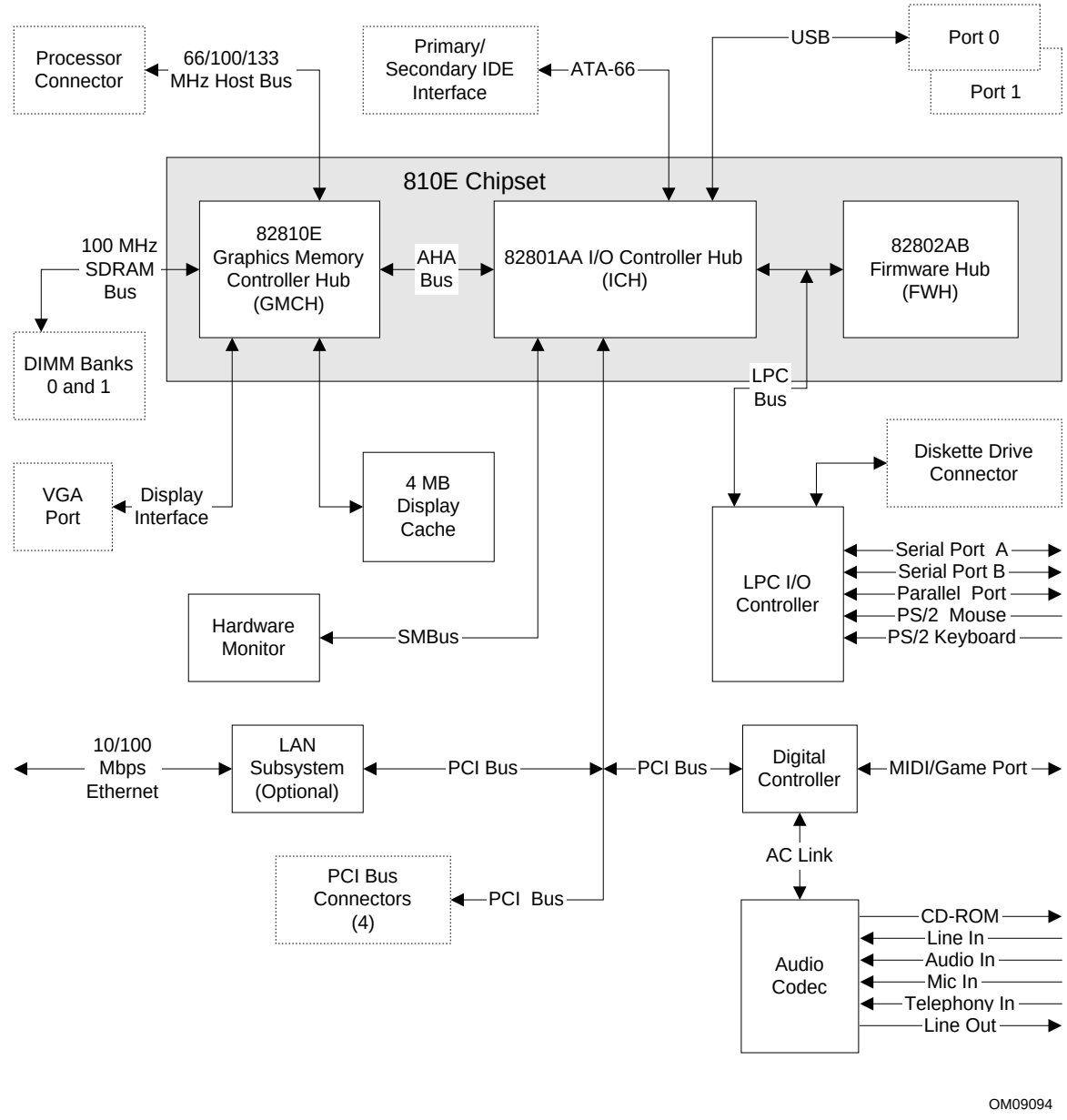


Figure 2. Board Block Diagram

1.2 Online Support

Find information about Intel boards under “Product Info” or “Customer Support” at these World Wide Web sites:

http://developer.intel.com/design/motherbd
http://support.intel.com/support/motherboards/desktop

Find “Processor Data Sheets” or information about “Proper Date Access in Systems with Intel Motherboards” at these World Wide Web sites:

http://www.intel.com/design/litcentr
http://support.intel.com/support/year2000

Find information about the ICH addressing at this World Wide Web site:
http://developer.intel.com/design/chipsets/datashts/

1.3 Design Specifications

Table 3 lists the specifications applicable to the CA810E board.

Table 3. Compliance with Specifications

Specification	Description	Revision Level
AC ‘97	Audio Codec ’97 Component Specification	Revision 2.1, May 22, 1998, Intel Corporation. This specification is available at: http://developer.intel.com/pc-supp/platform/ac97/
ACPI	Advanced Configuration and Power Interface specification	Revision 1.0a, July 1, 1998, Intel Corporation, Microsoft Corporation, and Toshiba Corporation. The specification is available at: http://www.teleport.com/~acpi/
AGP	Accelerated Graphics Port Interface Specification (1X and 2X)	Revision 2.0, May 4, 1998, Intel Corporation. The specification is available through the Accelerated Graphics Port Implementers Forum at: http://www.agpforum.org/
AMI BIOS	American Megatrends BIOS Specification	AMIBIOS 98. This specification is available at: http://www.amibios.com
AMR	Audio Modem Riser Specification	Revision 1.01, September 10, 1998, Intel Corporation. The specification is available at: ftp://download.intel.com/pc-supp/platform/ac97/amr101.pdf
APM	Advanced Power Management BIOS Interface Specification	Revision 1.2, February, 1996, Intel Corporation and Microsoft Corporation. This specification is available at: http://www.microsoft.com/hwdev/busbios/amp_12.htm
ATA-3	Information Technology - AT Attachment-3 Interface	X3T10/2008D Revision 6. The specification is available at the ATA Anonymous FTP Site: fission.dt.wdc.com.
ATAPI	ATA Packet Interface for CD-ROMs	SFF-8020i Revision 2.5. The specification is available at: (SFF) Fax at: (408) 741-1600

continued

Table 3. Compliance with Specifications (continued)

Specification	Description	Revision Level
ATX	ATX form factor specification	Revision 2.03, December 1998, Intel Corporation. The specification is available at: http://developer.intel.com/design/motherbd/atx.htm
DDC2B	Display Data Channel Standard	Version 3.0, Level 2B protocols, Video Electronics Standards Association (VESA). The specification is available at: http://www.vesa.org
El Torito	Bootable CD-ROM format specification	Version 1.0, January 25, 1995, Phoenix Technologies Ltd. And IBM Corporation. The specification is available at: http://www.phoenix.com/products/specs.html
EPP	Enhanced Parallel Port	IEEE 1284 standard, Mode [1 or 2], v1.7, v1.9
IrDA†	Serial Infrared Physical Layer Link specification	Version 1.1, October 17, 1995 Infrared Data Association. The specification is available at: Phone: (510) 943-6546 Fax: (510) 943-5600 E-mail: irda@netcom.com
microATX	microATX Motherboard Interface Specification	Version 1.0, December 1997, Intel Corporation. The specification is available at: http://www.teleport.com/~microatx/spec/
LPC	Low Pin Count Interface Specification	Revision 1.0, September 29, 1997, Intel Corporation. This specification is available at: http://www.intel.com/design/chipsets/industry/lpc.htm
PCI	PCI Local Bus Specification PCI Power Management Interface Specification	Revision 2.2, December 18, 1998, PCI Special Interest Group. Revision 1.1, December 18, 1998, PCI Special Interest Group. These specifications can be ordered at: http://www.pcisig.com/
Plug and Play	Plug and Play BIOS specification	Version 1.0a, May 5, 1994, Compaq Computer Corporation, Phoenix Technologies Ltd., and Intel Corporation. The specification is available at: ftp://download.intel.com/ial/wfm/bio10a.pdf
SDRAM DIMMs (64- and 72-bit)	PC SDRAM Unbuffered DIMM Specification PC SDRAM DIMM Specification PC Serial Presence Detect (SPD) Specification	Revision 1.0, February 1998, Intel Corporation. Revision 1.63, October 1998, Intel Corporation. Revision 1.2A, December 1997, Intel Corporation. These specifications are available at: http://developer.intel.com/design/chipsets/memory/

continued

Table 3. Compliance with Specifications (continued)

Specification	Description	Revision Level
SMBIOS	System Management BIOS Reference Specification	Version 2.3, August 12, 1998, American Megatrends Inc., Award Software International Inc., Compaq Computer Corporation, Dell Computer Corporation, Hewlett-Packard Company, Intel Corporation, Phoenix Technologies Ltd., and SystemSoft Corporation. The specification is available at: http://developer.intel.com/ial/WfM/design/smbios/
UHCI	Universal Host Controller Interface (UHCI) Design Guide	Revision 1.1, March 1996, Intel Corporation. This specification is available at: http://www.usb.org/developers/
USB	Universal serial bus specification	Revision 1.1, September 23, 1998, Compaq Computer Corporation, Intel Corporation, Microsoft Corporation, and NEC. This specification is available at: http://www.usb.org/developers/
WfM	Wired for Management Baseline Specification	Version 2.0, December 18, 1998, Intel Corporation. This specification is available at: http://developer.intel.com/ial/wfm/wfmspecs.htm

1.4 Processor

The CA810E board supports a single Pentium III processor with 100 MHz or 133 MHz host bus frequency, or a single Celeron processor with 66 MHz or 100 MHz host bus frequency. The processor's VID pins automatically program the voltage regulator on the board to the required processor voltage. The host bus speed for any of the processors is automatically selected. The processor connects to the board through the PGA370 socket.

The board supports the processors listed in Table 4.

Table 4. Processors Supported by the Board

Processor Speed	Processor Speed	Host Bus Frequency	Cache Size
Pentium III processor	500E MHz 550E MHz	100 MHz 100 MHz	256 KB 256 KB
Celeron processor	366 MHz 400 MHz 433 MHz 466 MHz 500 MHz	66 MHz 66 MHz 66 MHz 66 MHz 66 MHz	128 KB 128 KB 128 KB 128 KB 128 KB

All supported onboard memory can be cached, up to the cachability limit of the processor.

For information about	Refer to
Processor support for the CA810E board	Section 1.2, page 16
Processor data sheets	Section 1.2, page 16

1.5 System Memory

CAUTION

To be fully compliant with all applicable Intel® SDRAM memory specifications, the board should be populated with DIMMs that support the Serial Presence Detect (SPD) data structure. If your memory module does not support SPD, you will see a notification to this effect on the screen at power-up. The BIOS will attempt to configure the memory controller for normal operation; however, DIMMs may not function at the determined frequency.

CAUTION

*Because the main system memory is also used as video memory, the CA810E board requires 100 MHz SDRAM DIMMs. It is **highly** recommended that SPD DIMMs be used, since this allows the BIOS to read the SPD data and program the chipset to accurately configure memory settings for optimum performance. If non-SPD memory is installed, the BIOS will attempt to correctly configure the memory settings, but performance and reliability may be impacted.*

The board has two 3.3V, 168 pin DIMM sockets. SDRAM can be installed in one or both sockets. Minimum memory size is 16 MB; maximum memory size is 512 MB. The BIOS automatically detects memory type, size, and speed. Due to the video requirements of the CA810E board, most configurations require at least 64 MB of memory.

The board supports memory with the following features:

- 168-pin DIMMs with gold-plated contacts
- 100 MHz unbuffered SDRAM
- Non-ECC (64-bit) memory
- Serial Presence Detect (SPD) or non-SPD memory (BIOS recovery requires SPD DIMMs)
- 3.3 V memory only

The board supports single- or double-sided DIMMs in the following sizes:

DIMM Size	Non-ECC Configuration
16 MB	2 Mbit x 64
32 MB	4 Mbit x 64
64 MB	8 Mbit x 64
128 MB	16 Mbit x 64
256 MB	32 Mbit x 64

NOTE

256 MB DIMMs used with this board must be built with 128 Mbit device technology.

1.6 Intel® 810E Chipset

The Intel 810E chipset consists of the following devices:

- Graphics and Memory Controller Hub (GMCH)
- I/O Controller Hub (ICH)
- Firmware Hub (FWH)

The chipset provides the host, memory, graphics, and I/O interfaces shown in Figure 3.

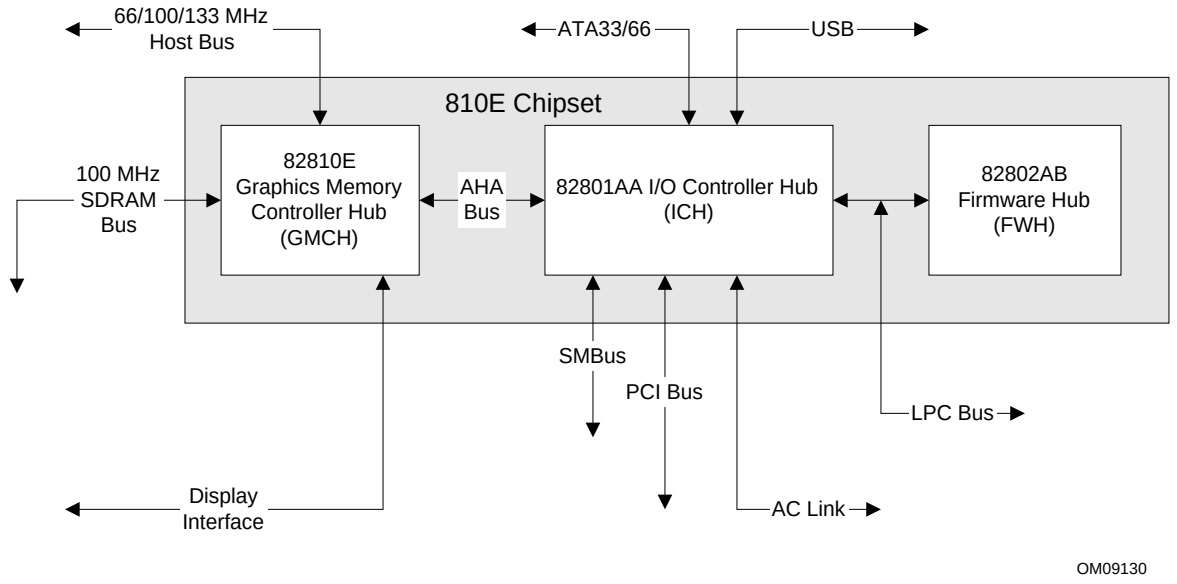


Figure 3. Intel 810E Chipset Block Diagram

For information about	Refer to
The Intel 810E chipset	http://developer.intel.com
The resources used by the chipset	Chapter 2
The chipset's compliance with ACPI, APM, AC '97	Section 1.3, page 16

1.6.1 USB

The board has two USB ports; one USB peripheral can be connected to each port. For more than two USB devices, an external hub can be connected to either port. The two USB ports are implemented with stacked back panel connectors. The board fully supports UHCI and uses UHCI-compatible software drivers.

USB features include:

- Self-identifying peripherals that can be plugged in while the computer is running
- Automatic mapping of function to driver and configuration
- Support for isochronous and asynchronous transfer types over the same set of wires
- Support for up to 127 physical devices
- Guaranteed bandwidth and low latencies appropriate for telephony, audio, and other applications
- Error-handling and fault-recovery mechanisms built into the protocol

NOTE

Computer systems that have an unshielded cable attached to a USB port may not meet FCC Class B requirements, even if no device or a low-speed USB device is attached to the cable. Use shielded cable that meets the requirements for full-speed devices.

For information about	Refer to
The location of the USB connectors on the back panel	Figure 7, page 46
The signal names of the USB connectors	Table 19, page 47
The USB specification and UHCI	Section 1.3, page 16
Routing USB to the front panel	Section 2.9.2, page 64

1.6.2 IDE Support

1.6.2.1 IDE Interfaces

The board has two independent bus-mastering IDE interfaces. These interfaces support:

- ATAPI devices (such as CD-ROM drives)
- Ultra ATA/33 and Ultra ATA/66 devices

The BIOS supports logical block addressing (LBA) and extended cylinder head sector (ECHS) translation modes. The drive reports the transfer rate and translation mode to the BIOS.

The board supports laser servo (LS-120) diskette technology through its IDE interfaces. The LS-120 drive can be configured as a boot device by setting the BIOS Setup program's Boot menu to one of the following:

- ARMD-FDD (ATAPI Removable Media Device - Floppy Disk Drive)
- ARMD-HDD (ATAPI Removable Media Device - Hard Disk Drive)

For information about	Refer to
The location of the IDE connectors	Figure 9, page 53
The signal names of the IDE connectors	Table 33, page 54
BIOS Setup program's Boot menu	Table 73, page 99

1.6.3 Real-Time Clock, CMOS SRAM, and Battery

The real-time clock is compatible with DS1287 and MC146818 components. The clock provides a time-of-day clock and a multicentury calendar with alarm features and century rollover. The real-time clock supports 256 bytes of battery-backed CMOS SRAM in two banks that are reserved for BIOS use.

The time, date, and CMOS values can be specified in the Setup program. The CMOS values can be returned to their defaults by using the Setup program.

NOTE

The recommended method of accessing the date in systems with Intel boards is from the Real-Time Clock (RTC) via the BIOS. The BIOS on Intel boards contains a century checking and maintenance feature that checks the least two significant digits of the year stored in the RTC during each BIOS request (INT 1Ah). During this check, the BIOS reads the date and, if less than 80 (i.e., 1980 is the first year supported by the PC), updates the century byte to 20. This feature enables operating systems and applications using the BIOS date/time services to reliably manipulate the year as a four-digit value.

A coin-cell battery powers the real-time clock and CMOS memory. When the computer is not plugged into a wall socket, the battery has an estimated life of three years. When the computer is plugged in, the 3.3 V standby current extends the life of the battery. The clock is accurate to ± 13 minutes/year at 25 ºC with 3.3 V applied.

For information about	Refer to
Proper date access in systems with Intel desktop boards	Section 1.2, page 16

1.7 I/O Controller

The SMSC LPC47M102 super I/O controller provides the following features:

- Low pin count (LPC) interface
- Two serial ports
- Infrared port (IrDA 1.1 compliant)
- One parallel port with Extended Capabilities Port (ECP) and Enhanced Parallel Port (EPP) support
- PS/2–style mouse and keyboard interfaces
- Interface for one 1.2 MB, 1.44 MB, or 2.88 MB diskette drive
- Intelligent power management, including a programmable wake up event interface
- Fan control:
  - Pulse width modulation (PWM) fan speed control output
  - Two fan tachometer inputs

The BIOS Setup program provides configuration options for the I/O controller.

For information about	Refer to
SMSC LPC47M102 I/O controller	http://www.smsc.com

1.7.1 Serial Port

The board has one 9-pin D-Sub serial port connector located on the back panel and a connector on the board for a second serial port. The serial ports' NS16C550-compatible UARTs support data transfers at speeds up to 115.2 with BIOS support. The serial ports can be assigned as COM1 (3F8h), COM2 (2F8h), COM3 (3E8h), or COM4 (2E8h).

For information about	Refer to
The location of the serial port connectors	Figure 7, page 46
The signal names of the serial port connectors	Table 22, page 49

1.7.2 Infrared Support

On the front panel connector, there are four pins that support Hewlett Packard HSDL-1000 compatible infrared (IR) transmitters and receivers. In the BIOS Setup program, Serial Port B can be directed to a connected IR device. The IR connection can be used to transfer files to or from portable devices like laptops, PDAs, and printers. The Infrared Data Association (IrDA) specification supports data transfers of 115.2 kbits/sec at a distance of 1 meter.

For information about	Refer to
The infrared port connector	Table 43, page 61
Configuring serial port B for infrared applications	Section 4.4.3, page 90
The IrDA specification	Section 1.3, page 16

1.7.3 Parallel Port

The connector for the multimode bidirectional parallel port is a 25-pin D-Sub connector located on the back panel of the board. In the Setup program, there are four options for parallel port operation:

- Output Only
- Bidirectional (PS/2 compatible)
- EPP
- ECP

For information about	Refer to
The location of the parallel port connector	Figure 7, page 46
The signal names of the parallel port connector	Table 21, page 48

1.7.4 Diskette Drive Controller

The I/O controller supports a single diskette drive that is compatible with the 82077 diskette drive controller and supports both PC-AT† and PS/2 modes.

NOTE

The I/O controller supports 1.2 MB, 3.5-inch diskette drives, but a special driver is required for this type of drive.

For information about	Refer to
The location of the diskette drive connector	Figure 9, page 53
The signal names of the diskette drive connector	Table 34, page 54
The supported diskette drive capacities and sizes	Table 68, page 94

1.7.5 Keyboard and Mouse Interface

PS/2 keyboard and mouse connectors are located on the back panel of the board. The +5 V lines to these connectors are protected with a PolySwitch† circuit that, like a self-healing fuse, reestablishes the connection after an overcurrent condition is removed.

NOTE

Power to the computer should be turned off before a keyboard or mouse is connected or disconnected.

The keyboard controller contains code that provides the traditional keyboard and mouse control functions and also supports Power On/Reset password protection. A Power On/Reset password can be specified in the BIOS Setup program.

For information about	Refer to
The location of the keyboard and mouse connectors	Figure 7, page 46
The signal names of the keyboard and mouse connectors	Table 17, page 47

1.8 Graphics Subsystem

The graphics subsystem features the Intel 82810E DC-133 Graphics and Memory Controller Hub (GMCH):

- Integrated graphics controller
  - 3-D Hyper Pipelined architecture
  - Full 2-D hardware acceleration
  - Motion video acceleration
- 3-D graphics visual and texturing enhancements
- Display
  - Integrated 24-bit 230 MHz RAMDAC
  - Display Data Channel Standard, Version 3.0, Level 2B protocols compliant (see Section 1.3 for specification information)
- Video
  - Hardware motion compensation for software MPEG2 decode
  - Software DVD at 30 fps
- Integrated graphics memory controller
- 4 MB of 133 MHz onboard video display cache

For information about	Refer to
The GMCH	Section 1.2, page 16

Table 5 lists the refresh rates supported by the CA810E board.

Table 5. Intel 82810 GMCH Refresh Rates

Resolution	Colors	60 Hz	70 Hz	72 Hz	75 Hz	85 Hz
640x480	16	x	x	x	x	x
	256	x	x	x	x	x
	64 K	x	x	x	x	x
	16 M	x	X	x	x	x
720x480	256				x	x
	64 K				x	x
	16 M				x	x
720x576	256				x	x
	64 K				x	x
	16 M				x	x
800x600	256	x	X	x	x	x
	64 K	x	X	x	x	x
	16 M	x	X	x	x	x
1024x768	256	x	X		x	x
	64 K	x	X		x	x
	16 M	x	X		x	x
1152x864	256	x	X	x	x	x
	64 K	x	X	x	X	x
	16 M	x			X	x
1280x1024	256	x	X	x	X	x
	64 K	x	X	x	X	x
	16 M	x	X		X	x
1600x1200	256	x	X	x	X	

NOTE

Some of the system memory is reserved for video.

1.9 Audio Subsystem

The Audio Codec ’97 (AC ’97) compatible audio subsystem includes these features:

- Split digital/analog architecture for improved signal-to-noise ratio (≥ 85 dB) measured at line out, from any analog input, including line in, CD-ROM, and auxiliary line in
- 3-D stereo enhancement
- Power management support for APM 1.2 and ACPI 1.0a

The audio subsystem consists of these devices:

- Creative Sound Blaster AudioPCI 128V audio solution
- Crystal Semi conductor CS4297 stereo audio codec
- Audio connectors

For information about	Refer to
Obtaining audio software and utilities	Paragraph 1.2, page 16

1.9.1 Creative Sound Blaster AudioPCI 128V Audio Solution

The Creative Sound Blaster AudioPCI 128V solution features:

- Creative ES1373 controller
- Interfaces to PCI bus as a Plug and Play device
- 100% DOS legacy compatible
- Access to main memory (through the PCI bus) for wavetable synthesis support – does not require a separate wavetable ROM device
- Conforms to the PC 98 and PC 99 design guides

For information about	Refer to
Creative Sound Blaster AudioPCI 128V	http://www.soundblaster.com

1.9.2 Crystal Semiconductor CS4297 Stereo Audio Codec

The Crystal Semiconductor CS4297 stereo audio codec features:

- High performance 18-bit stereo full-duplex audio codec with up to 48 KHz sampling rate
- Connects to the Sound Blaster AudioPCI 128V using a five-wire digital interface

1.9.3 Audio Connectors

The audio connectors include the following:

- Legacy-style CD-ROM connector
- ATAPI-style connectors
  - CD-ROM
  - Auxiliary line in (optional)
  - Telephony (optional)
  - Video source line in (optional)
- Back panel connectors
  - Line out
  - Line in
  - Mic in
  - MIDI/Game Port

NOTE

The line out connector, located on the back panel, is designed to power either headphones or amplified speakers only. Poor audio quality may occur if passive (non-amplified) speakers are connected to this output.

For information about	Refer to
The back panel audio connectors	Section 2.8.1, page 46

1.9.3.1 Legacy CD-ROM (2 mm) Connector

A 1 x 4-pin legacy-style 2 mm connector connects an internal CD-ROM drive to the audio mixer.

For information about	Refer to
The location of the legacy CD-ROM connector	Figure 8, page 51
The signal names of the legacy CD-ROM connector	Table 28, page 52

1.9.3.2 ATAPI CD-ROM Audio Connector

A 1 x 4-pin ATAPI connector connects an internal CD-ROM drive to the audio mixer.

For information about	Refer to
The location of the ATAPI CD-ROM connector	Figure 8, page 51
The signal names of the ATAPI CD-ROM connector	Table 27, page 52

1.9.3.3 Auxiliary Line In Connector (Optional)

A 1 x 4-pin ATAPI-style connector connects the left and right channel signals of an internal audio device to the audio subsystem.

For information about	Refer to
The location of the auxiliary line in connector	Figure 8, page 51
The signal names of the auxiliary line in connector	Table 30, page 52

1.9.3.4 Telephony Connector (Optional)

A 1 x 4-pin ATAPI-style connector connects the monaural audio signals of an internal telephony device to the audio subsystem. A monaural audio-in and audio-out signal interface is necessary for telephony applications such as speakerphones, fax/modems, and answering machines.

For information about	Refer to
The location of the telephony connector	Figure 8, page 51
The signal names of the telephony connector	Table 31, page 52

1.9.3.5 Video Source Line In Connector (Optional)

A 1 x 4 pin ATAPI style connector connects the left and right audio channel signals of an internal video device to the audio subsystem. An audio-in signal interface of this type is necessary for applications such as TV tuners.

For information about	Refer to
The location of the video source line in connector	Figure 8, page 51
The signal names of the video source line in connector	Table 29, page 52

1.10 Hardware Management Features

The hardware management features enable the board to be compatible with the Wired for Management (WfM) specification. The board has several hardware management features, including the following:

- Hardware monitor component (optional)
- Alert on LAN component (optional)
- Chassis intrusion detect connector (optional)
- Fan control and monitoring (implemented on the SMSC LPC47M102 super I/O controller)

1.10.1 Hardware Monitor Component (Optional)

The optional hardware monitor component provides low-cost instrumentation capabilities. The features of the component include:

- Internal ambient temperature sensing
- Remote thermal diode sensing for direct monitoring of processor temperature
- Power supply monitoring (+12, +5, +3.3, +2.5, V_{CCP}) to detect levels above or below acceptable values
- SMBus interface

1.10.2 Alert on LAN Component (Optional)

The Alert on LAN component is a companion device to the 82559 LAN controller. Together, the two devices provide a management interface between a remote console (or management server) and the client system monitoring instrumentation (the ICH and/or the hardware monitor component). The functions of the alert on LAN component include:

- Sending alert (SOS), heartbeat, or pong (ping response) packets to the 82559 LAN controller
- Receiving specially filtered packets needed for advanced power management modes such as reset, power-up, or power-down

1.10.3 Chassis Intrusion Detect Connector (Optional)

The board supports a chassis security feature that detects if the chassis cover is removed and sounds an alarm (through the onboard speaker or PC chassis speaker, if either is present). For the chassis intrusion circuit to function, the chassis' power supply must be connected to AC power. The security feature uses a mechanical switch on the chassis that attaches to the chassis intrusion detect connector. The mechanical switch is closed for normal computer operation.

For information about	Refer to
The location of the chassis intrusion detect connector	Figure 10, page 56
The signal names of the chassis intrusion detect connector	Table 41, page 57

1.11 LAN Subsystem (Optional)

The optional Intel 82559 Fast Ethernet Wired for Management (WfM) PCI LAN subsystem provides both 10Base-T and 100Base-TX connectivity. Features include:

- 32-bit, 33 MHz direct bus mastering on the PCI bus
- Shared memory structure in the host memory that copies data directly to/from host memory
- 10Base-T and 100Base-TX capability using a single RJ-45 connector with connection and activity status LEDs
- IEEE 802.3u Auto-Negotiation for the fastest available connection
- Jumperless configuration; the LAN subsystem is completely software-configurable

For information about	Refer to
The WfM specification	Section 1.3, page 16

1.11.1 Intel® 82559 PCI LAN Controller

The Intel 82559 PCI LAN controller's features include:

- CSMA/CD Protocol Engine
- PCI bus interface
- DMA engine for movement of commands, status, and network data across the PCI bus
- Integrated physical layer interface, including:
  - — Complete functionality necessary for the 10Base-T and 100Base-TX network interfaces; when in 10 Mbit/sec mode, the interface drives the cable directly
  - — A complete set of Media Independent Interface (MII) management registers for control and status reporting
  - — 802.3u Auto-Negotiation for automatically establishing the best operating mode when connected to other 10Base-T or 100Base-TX devices, whether half- or full-duplex capable
- Integrated power management features, including:
  - — Support for APM
  - — Support for Wake on LAN† technology

For information about	Refer to
The LAN subsystem's PCI specification compliance	Section 1.3, page 16

1.11.2 LAN Subsystem Software

The Intel 82559 Fast Ethernet WfM PCI LAN software and drivers are available from Intel's World Wide Web site.

For information about	Refer to
Obtaining LAN software and drivers	http://support.intel.com/support/motherboards/desktop

1.11.3 RJ-45 LAN Connector LEDs

Two LEDs are built into the RJ-45 LAN connector. Table 6 describes the LED states when the board is powered up and the LAN subsystem is operating.

Table 6. RJ-45 LAN Connector LEDs

LED Color	LED State	Indicates
Green	Off	10 Mbit/sec speed is selected.
	On	100 Mbit/sec speed is selected.
Yellow	Off	LAN link is not established.
	On (steady state)	LAN link is established.
	On (brighter and pulsing)	The computer is communicating with another computer on the LAN.

1.12 Power Management Features

Power management is implemented at several levels, including:

- Software support:
  - Advanced Power Management (APM)
  - Advanced Configuration and Power Interface (ACPI)
- Hardware support:
  - Wake on LAN technology
  - Instantly Available technology
  - Resume on Ring

1.12.1 Software Support

The software support for power management includes:

- APM
- ACPI

If the board is used with an ACPI-aware operating system, the BIOS can provide ACPI support. Otherwise, it defaults to APM support.

1.12.1.1 APM

APM makes it possible for the computer to enter an energy saving standby mode. The standby mode can be initiated in the following ways:

- Time-out period specified in the BIOS Setup program
- Suspend/resume switch connected to the front panel sleep connector
- From the operating system, such as the Suspend menu item in Windows† 98

In standby mode, the board can reduce power consumption by spinning down hard drives, and reducing power to or turning off VESA DPMS-compliant monitors. Power-management mode can be enabled or disabled in the BIOS Setup program.

While in standby mode, the system retains the ability to respond to external interrupts and service requests, such as incoming faxes or network messages. Any keyboard or mouse activity brings the system out of standby mode and immediately restores power to the monitor.

The BIOS enables APM by default; but the operating system must support an APM driver for the power-management features to work. For example, Windows 98 supports the power-management features upon detecting that APM is enabled in the BIOS.

For information about	Refer to
Enabling or disabling power management in the BIOS Setup program	Section 4.6, page 98
The board's compliance level with APM	Table 3, page 16

1.12.1.2 ACPI

ACPI gives the operating system direct control over the power management and Plug and Play functions of a computer. The use of ACPI with this board requires the support of an operating system that provides full ACPI functionality. ACPI features include:

- Plug and Play (including bus and device enumeration) and power management normally contained in the BIOS
- Power management control of individual devices, add-in boards (some add-in boards may require an ACPI-aware driver), video displays, and hard disk drives
- Methods for achieving less than 30-watt system operation in the Power On Suspend sleeping state, and less than 5-watt system operation in the Suspend to Disk sleeping state
- A Soft-off feature that enables the operating system to power off the computer
- Support for multiple wake up events (see Table 9 on page 33)
- Support for a front panel power and sleep mode switch. Table 7 lists the system states based on how long the power switch is pressed, depending on how ACPI is configured with an ACPI-aware operating system.

Table 7. Effects of Pressing the Power Switch

If the system is in this state…		…and the power switch is pressed for	…the system enters this state
Off	(ACPI G2/S5 state)	Less than four seconds	Power on
On	(ACPI G0 state)	Less than four seconds	Soft off/Suspend
On	(ACPI G0 state)	More than four seconds	Fail safe power off
Sleep	(ACPI G1 state)	Less than four seconds	Wake up
Sleep	(ACPI G1 state)	More than four seconds	Power off

NOTE

The optional Wake on LAN technology connector at location J8A3 is provided to support wake up from a LAN adapter in APM mode. Wake on LAN technology in ACPI mode is supported via the PME# signal on the PCI connector.

For information about	Refer to
The board's compliance level with ACPI	Section 1.3, page 16

1.12.1.2.1 System States and Power States

Under ACPI, the operating system directs all system and device power state transitions. The operating system puts devices in and out of low-power states based on user preferences and knowledge of how devices are being used by applications. Devices that are not being used can be turned off. The operating system uses information from applications and user settings to put the system as a whole into a low-power state.

Table 8 lists the power states supported by the board along with the associated system power targets. See the ACPI specification for a complete description of the various system and power states.

Table 8. Power States and Targeted System Power

Global States	Sleeping States	CPU States	Device States	Targeted System Power*
G0 - working state	S0 - working	C0 - working	D0 - working state	Full power > 30 W
G1 - sleeping state	S1 - CPU stopped	C1 - stop grant	D1, D2, D3 - device specification specific.	5 W < power < 30 W
G1 - sleeping state	S3 - Suspend-to-RAM Context saved to RAM	No power	D3 - no power except for wake up logic.	Power < 5 W **
G2/S5	S5 - Soft off. Context not saved. Cold boot is required.	No power	D3 - no power except for wake up logic.	Power < 5 W **
G3 - mechanical off AC power is disconnected from the computer.	No power to the system.	No power	D3 - no power for wake up logic, except when provided by battery or external source.	No power to the system so that service can be performed.

* Total system power is dependent on the system configuration, including add-in boards and peripherals powered by the system chassis' power supply.

** Dependent on the standby power consumption of wake-up devices used in the system.

1.12.1.2.2 Wake Up Devices and Events

Table 9 lists the devices or specific events that can wake the computer from specific states. Sleeping state S5 is the same for the wake up event.

Table 9. Wake Up Devices and Events

These devices/events can wake up the computer…	…from this state
Power switch	S1, S3, S5
RTC alarm	S1, S3, S5
LAN (S5 state requires a Wake on LAN technology header)	S1, S3, S5
Modem	S1, S3
IR command	S1
USB	S1
PS/2 keyboard	S1
PS/2 mouse	S1
Sleep button	S1
PME	S1, S3

1.12.1.2.3 Plug and Play

In addition to power management, ACPI provides controls and information so that the operating system can facilitate Plug and Play device enumeration and configuration. ACPI is used only to enumerate and configure board devices that do not have other hardware standards for enumeration and configuration. PCI devices on the board, for example, are not enumerated by ACPI.

1.12.2 Hardware Support

The board provides several hardware features that support power management, including:

- Wake on LAN technology
- Instantly Available technology
- Resume on Ring
- Fan connectors

Wake on LAN technology and Instantly Available technology require power from the +5 V standby line. The sections discussing these features describe the incremental standby power requirements for each.

⚠ CAUTION

If Wake on LAN and Instantly Available technology features are used, ensure that the power supply provides adequate +5 V standby current. Failure to do so can damage the power supply. The total amount of standby current required depends on the wake devices supported and manufacturing options.

Resume on Ring enables telephony devices to access the computer when it is in a power-managed state. The method used depends on the type of telephony device (external or internal) and the power management mode being used (APM or ACPI).

NOTE

The use of Resume on Ring technology from an ACPI state requires the support of an operating system that provides full ACPI functionality.

1.12.2.1 Wake on LAN Technology

Wake on LAN technology enables remote wakeup of the computer through a network. The LAN subsystem, whether onboard or as a PCI bus network adapter, monitors network traffic at the Media Independent Interface. Upon detecting a Magic Packet† frame, the LAN subsystem asserts a wakeup signal that powers up the computer. Depending on the LAN implementation, the board supports Wake on LAN technology in one of two ways:

- Through the Wake on LAN technology connector
- Through the PCI bus PME# signal (for PCI 2.2 compliant LAN designs)

The Wake on LAN technology connector can be used with PCI bus network adapters that have a remote wake up connector, as shown in Figure 4. Network adapters that are PCI 2.2 compliant assert the wakeup signal through the PCI bus signal PME# (pin A19 on the PCI bus connectors). The optional onboard LAN subsystem also supports remote wakeup using the PME# signal.

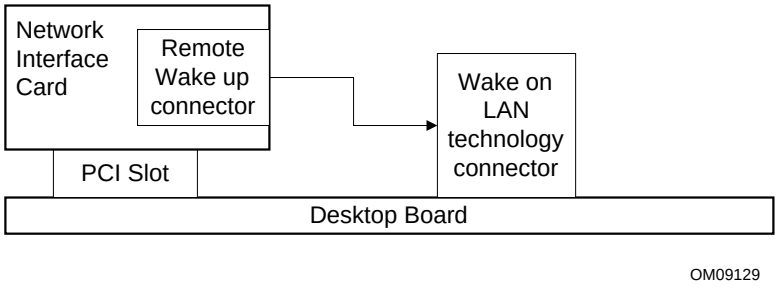


Figure 4. Using the Wake on LAN Technology Connector

For information about	Refer to
The location of Wake on LAN technology connector	Figure 10, page 56
The signal names of the Wake on LAN technology connector	Table 40, page 57

1.12.2.2 Instantly Available Technology

CAUTION

For Instantly Available technology, the power supply must be capable of providing the +5 V standby current that those boards require in addition to the standby current required by the board. Failure to provide adequate standby current when using this feature can damage the power supply. Refer to Section 2.11.3 on page 68 for more information.

Instantly Available technology enables the board to enter the ACPI S3 (Suspend-to-RAM) sleep state. While in the S3 sleep state, the computer will appear to be off. When signaled by a wake up device or event, the system quickly returns to its last known wake state. Table 9 on page 33 lists the devices and events that can wake the computer from the S3 state.

The board supports the *PCI Bus Power Management Interface Specification* and the 3.3V Aux ECR. Add-in boards that also support these specifications can participate in power management and can be used to wake the computer.

The standby power indicator (located between the DIMM sockets and the power connector) provides an indication that power is still present to the DIMMs and PCI bus connectors, even when the computer appears to be off. Figure 5 shows the location of the standby power LED.

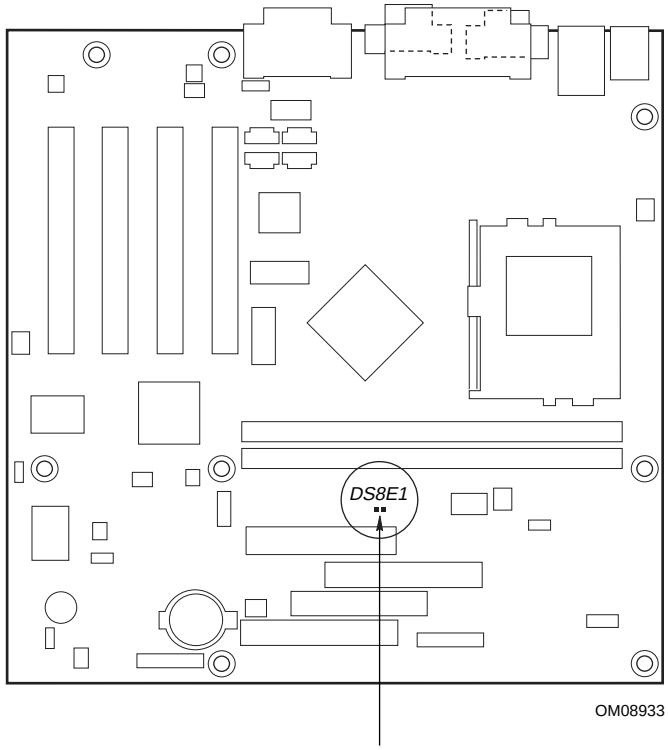


Figure 5. Location of Standby Power Indicator LED

1.12.2.3 Resume on Ring

The operation of Resume on Ring can be summarized as follows:

- Resumes operation from either the APM sleep mode or the ACPI S1 state
- Requires only one call to access the computer
- Detects incoming call similarly for external and internal modems
- Requires modem interrupt be unmasked for correct operation

1.12.2.4 Fan Connectors

The board has three fan connectors, one being a manufacturing option. The functions of these connectors are described in Table 10.

Table 10. Fan Connector Descriptions

Connector	Function
Fan 1 (chassis fan)	Provides +12 V DC for a system or chassis fan. The fan voltage can be switched on or off, depending on the power management state of the computer. A tachometer feedback connection is also provided.
Fan 2 (processor fan)	Provides +12 V DC for a system or chassis fan. The fan voltage can be switched on or off, depending on the power management state of the computer. A tachometer feedback connection is also provided.
Fan 3 (optional)	Provides +12 V DC without tachometer feedback connection.

NOTE

The on/off control and tachometer feedback connection for fan 1 and fan 2 are only available with the hardware monitor option.

2 Technical Reference

What This Chapter Contains

2.1 Introduction

Sections 2.2 – 2.6 contain several standalone tables. Table 11 describes the system memory map, Table 12 lists the DMA channels, Table 13 shows the I/O map, Table 14 defines the PCI configuration space map, and Table 15 describes the interrupts. The remaining sections in this chapter are introduced by text found with their respective section headings.

2.2 Memory Map

Table 11. System Memory Map

Address Range (decimal)	Address Range (hex)	Size	Description
1024 K - 524288 K	100000 - 1FFFFFFF	511 MB	Extended memory
960 K - 1024 K	F0000 - FFFFF	64 KB	Runtime BIOS
896 K - 960 K	E0000 - EFFFF	64 KB	Reserved
800 K - 896 K	C8000 - DFFFF	96 KB	Available high DOS memory (open to PCI bus)
640 K - 800 K	A0000 - C7FFF	160 KB	Video memory and BIOS
639 K - 640 K	9FC00 - 9FFFF	1 KB	Extended BIOS data (movable by memory manager software)
512 K - 639 K	80000 - 9FBFF	127 KB	Extended conventional memory
0 K - 512 K	00000 - 7FFFF	512 KB	Conventional memory

2.3 DMA Channels

Table 12. DMA Channels

DMA Channel Number	Data Width	System Resource
0	8- or 16-bits	Open
1	8- or 16-bits	Parallel port
2	8- or 16-bits	Diskette drive
3	8- or 16-bits	Parallel port (for ECP or EPP)
4		DMA controller
5	16-bits	Open
6	16-bits	Open
7	16-bits	Open

2.4 I/O Map

Table 13. I/O Map

Address (hex)	Size	Description
0000 - 000F	16 bytes	DMA controller
0020 - 0021	2 bytes	Programmable Interrupt Control (PIC)
0040 - 0043	4 bytes	System timer
0060	1 byte	Keyboard controller byte—reset IRQ
0061	1 byte	System speaker
0064	1 byte	Keyboard controller, CMD/STAT byte
0070 - 0071	2 bytes	System CMOS/Real Time Clock
0072 - 0073	2 bytes	System CMOS
0080 - 008F	16 bytes	DMA controller
0092	1 byte	Fast A20 and PIC
00A0 - 00A1	2 bytes	PIC
00B2 - 00B3	2 bytes	APM control
00C0 - 00DF	32 bytes	DMA
00F0	1 byte	Numeric data processor
0170 - 0177	8 bytes	Secondary IDE channel
01F0 - 01F7	8 bytes	Primary IDE channel
One of these ranges: 0200 - 0207 0208 - 020F 0210 - 0217 0218 - 021F	Can vary from 1 byte to 8 bytes	Audio/game port
One of these ranges:		Audio (Sound Blaster Pro† -compatible)
0220 - 022F	16 bytes	
0240 - 024F	16 bytes	
0228 - 022F*	8 bytes	LPT3
0278 - 027F*	8 bytes	LPT2
02E8 - 02EF*	8 bytes	COM4/video (8514A)
02F8 - 02FF*	8 bytes	COM2
One of these ranges: 0320 - 0327 0330 - 0337 0340 - 0347 0350 - 0357	8 bytes	MPU-401 (MIDI)
0376	1 byte	Secondary IDE channel command port
0377, bits 6:0	7 bits	Secondary IDE channel status port
0378 - 037F	8 bytes	LPT1
0388- 038B	6 bytes	AdLib† (FM synthesizer)
03B0 - 03BB	12 bytes	Intel 82810E DC-133 GMCH
03C0 - 03DF	32 bytes	Intel 82810E DC-133 GMCH
03E8 - 03EF	8 bytes	COM3

continued

Table 13. I/O Map (continued)

Address (hex)	Size	Description
03F0 - 03F5	6 bytes	Diskette channel 1
03F6	1 byte	Primary IDE channel command port
03F8 - 03FF	8 bytes	COM1
04D0 - 04D1	2 bytes	Edge/level triggered PIC
One of these ranges: 0530 – 0537 0E80 - 0E87 0F40 - 0F47	8 bytes	Windows Sound System
LPTn + 400	8 bytes	ECP port, LPTn base address + 400h
0CF8 - 0CFB**	4 bytes	PCI configuration address register
0CF9***	1 byte	Turbo and reset control register
0CFC - 0CFF	4 bytes	PCI configuration data register
FFA0 - FFA7	8 bytes	Primary bus master IDE registers
FFA8 – FFAF	8 bytes	Secondary bus master IDE registers
96 contiguous bytes starting on a 128-byte divisible boundary		ICH (ACPI + TCO)
64 contiguous bytes starting on a 64-byte divisible boundary		Board resource
64 contiguous bytes starting on a 64-byte divisible boundary		Onboard audio controller
32 contiguous bytes starting on a 32-byte divisible boundary		ICH (USB)
16 contiguous bytes starting on a 16-byte divisible boundary		ICH (SMB)
4096 contiguous bytes starting on a 4096-byte divisible boundary		Intel 82810AA PCI bridge
32 contiguous bytes starting on a 32-byte divisible boundary		Intel 82559 LAN controller (optional)

* Default, but can be changed to another address range.

** Dword access only

*** Byte access only

NOTE

Some additional I/O addresses are not available due to ICH addresses aliassing. For information about the ICH addressing, refer to Section 1.2 on page 16.

2.5 PCI Configuration Space Map

Table 14. PCI Configuration Space Map

Bus Number (hex)	Device Number (hex)	Function Number (hex)	Description
00	00	00	Intel 82810E GMCH (memory controller hub)
00	01	00	Intel 82810E GMCH (graphics controller hub)
00	1E	00	Hub link to PCI bridge
00	1F	00	Intel 82801AA ICH (I/O controller hub) PCI to LPC bridge
00	1F	01	IDE
00	1F	02	USB
00	1F	03	SMBUS
00	1F	05	AC ’97 audio controller or reserved
00	1F	06	AC ’97 modem controller or reserved
01	01	00	Intel 82559 LAN controller (optional)
01	07	00	Creative Sound Blaster AudioPCI 128V
01	08	00	PCI bus connector 1 (J4C1)
01	09	00	PCI bus connector 2 (J4B1)
01	0A	00	PCI bus connector 3 (J4A2)
01	0B	00	PCI bus connector 4 (J4A1)

2.6 Interrupts

Table 15. Interrupts

IRQ	System Resource
NMI	I/O channel check
0	Reserved, interval timer
1	Reserved, keyboard buffer full
2	Reserved, cascade interrupt from slave PIC
3	COM2* (user available if COM2 is not present)
4	COM1*
5	LPT2 (Plug and Play option)/audio/user available
6	Diskette drive controller
7	LPT1*
8	Real time clock
9	User available
10	User available
11	User available
12	Onboard mouse port (if present, else user available)
13	Reserved, math coprocessor
14	Primary IDE (if present, else user available)
15	Secondary IDE (if present, else user available)

* Default, but can be changed to another IRQ

2.7 PCI Interrupt Routing Map

This section describes interrupt sharing and how the interrupt signals are connected between the PCI expansion slots and onboard PCI devices. The PCI specification specifies how interrupts can be shared between devices attached to the PCI bus. In most cases, the small amount of latency added by interrupt sharing does not affect the operation or throughput of the devices. In some special cases where maximum performance is needed from a device, a PCI device should not share an interrupt with other PCI devices. Use the following information to avoid sharing an interrupt with a PCI add-in card.

PCI devices are categorized as follows to specify their interrupt grouping:

- INTA: By default, all add-in cards that require only one interrupt are in this category. For almost all cards that require more than one interrupt, the first interrupt on the card is also classified as INTA.
- INTB: Generally, the second interrupt on add-in cards that require two or more interrupts is classified as INTB. (This is not an absolute requirement.)
- INTC and INTD: Generally, a third interrupt on add-in cards is classified as INTC and a fourth interrupt is classified as INTD.

The ICH has four programmable interrupt request (PIRQ) input signals. Any PCI interrupt source (either onboard or from a PCI add-in card) connects to one of these PIRQ signals. Because there are only four signals, some PCI interrupt sources are mechanically tied together on the board and therefore share the same interrupt. Table 16 shows an example of how the PIRQ signals might be connected to the onboard graphics controller.

Table 16. PCI Interrupt Routing Map

PCI Interrupt Source	ICH PIRQ Signal Name			
	PIRQA	PIRQB	PIRQC	PIRQD
Graphics Controller Hub	INTA			
Intel 82559 LAN				INTA
ICH USB Controller				INTD
PCI Audio			INTA	
PCI Bus Connector 1 (J4C1)	INTA	INTB	INTC	INTD
PCI Bus Connector 2 (J4B1)	INTD	INTA	INTB	INTC
PCI Bus Connector 3 (J4A2)	INTC	INTD	INTA	INTB
PCI Bus Connector 4 (J4A1)	INTB	INTC	INTD	INTA
SMBUS Controller		INTB		

For example, assume an add-in card with one interrupt (group INTA) is inserted into PCI bus connector 4. In this slot, an interrupt source from group INTA connects to the PIRQD signal, which is already connected to the LAN and USB PCI sources. The add-in card shares an interrupt with these onboard interrupt sources.

⟹ NOTE

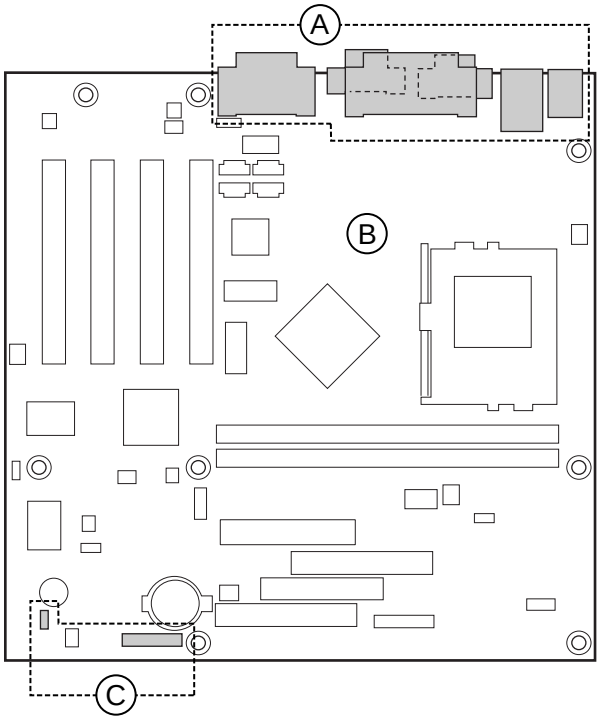
The ICH can connect each PIRQ line internally to one of the IRQ signals (3, 4, 5, 7, 9, 10, 11, 14, and 15). Typically, a device that does not share a PIRQ line will have a unique interrupt. However, in certain interrupt-constrained situations, it is possible for two or more of the PIRQ lines to be connected to the same IRQ signal.

2.8 Connectors

CAUTION

Only the back panel connectors of this CA810E board have overcurrent protection. The internal CA810E board connectors do not have overcurrent protection; they should connect only to devices inside the computer chassis, such as fans and internal peripherals. Do not use these connectors for powering devices external to the computer chassis. A fault in the load presented by the external devices could cause damage to the computer, the interconnecting cable, and the external devices themselves.

This section describes the board's connectors. The connectors can be divided into three groups, as shown in Figure 6.



A. Back panel connectors (see page 46)

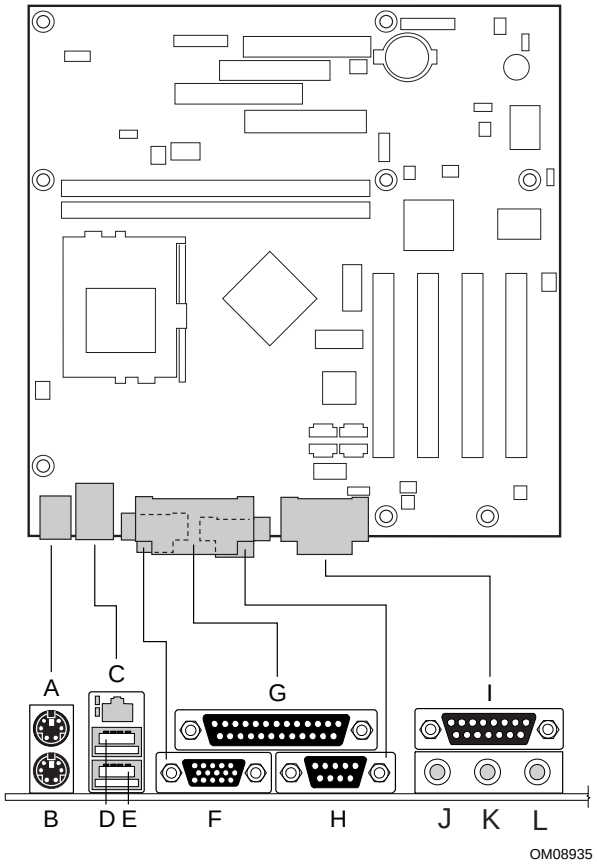
B. Midboard connectors (see page 50)

C. Front panel connectors (see page 60)

Figure 6. Connector Groups

2.8.1 Back Panel Connectors

Figure 7 shows the location of the back panel connectors. The back panel connectors are color-coded in compliance with PC 99 recommendations. The figure legend below lists the colors used.



Item	Description	Color	For more information see:
A	PS/2 mouse	Green	Table 17
B	PS/2 keyboard	Purple	Table 17
C	RJ-45 LAN (optional)		Table 18
D	USB port 0	Black	Table 19
E	USB port 1	Black	Table 19
F	VGA port	Dark blue	Table 20
G	Parallel port	Burgundy	Table 21
H	Serial port A	Teal	Table 22
I	MIDI/Game port	Gold	Table 23
J	Audio line out	Lime green	Table 24
K	Audio line in	Light blue	Table 25
L	Mic in	Pink	Table 26

Figure 7. Back Panel Connectors and Indicators

Table 17. PS/2 Keyboard/Mouse Connectors

Pin	Signal
1	Data
2	Not connected
3	Ground
4	Fused +5 V
5	Clock
6	Not connected

Table 18. RJ-45 LAN Connector (Optional)

Pin	Signal Name
1	TxD +
2	TxD -
3	RxD +
4	Ground
5	Ground
6	RxD -
7	Ground
8	Ground

Table 19. USB Connectors

Pin	Signal
1	Fused +5 V
2	3.3V differential USB signal USB_D0– (USB_D1–)
3	3.3V differential USB signal USB_D0+ (USB_D1+)
4	Ground

Table 20. VGA Connector

Pin	Signal
1	RED
2	GREEN
3	BLUE
4	Not connected
5	GND
6	GND
7	GND
8	GND
9	FUSED VCC
10	GND
11	Not connected
12	DDC_SDA
13	HSYNC
14	VSYNC
15	DDC_SCL

Table 21. Parallel Port Connector

Pin	Std Signal	ECP Signal	EPP Signal	I/O
1	STROBE#	STROBE#	WRITE#	I/O
2	PD0	PD0	PD0	I/O
3	PD1	PD1	PD1	I/O
4	PD2	PD2	PD2	I/O
5	PD3	PD3	PD3	I/O
6	PD4	PD4	PD4	I/O
7	PD5	PD5	PD5	I/O
8	PD6	PD6	PD6	I/O
9	PD7	PD7	PD7	I/O
10	ACK#	ACK#	INTR	I
11	BUSY	BUSY#, PERIPHACK	WAIT#	I
12	PERROR	PE, ACKREVERSE#	PE	I
13	SELECT	SELECT	SELECT	I
14	AUDOFD#	AUDOFD#, HOSTACK	DATASTB#	O
15	FAULT#	FAULT#, PERIPHREQST#	FAULT#	I
16	INIT#	INIT#, REVERSERQST#	RESET#	O
17	SLCTIN#	SLCTIN#	ADDRSTB#	O
18 - 25	GND	GND	GND	-

Table 22. Serial Port A Connector

Pin	Signal
1	DCD (Data Carrier Detect)
2	SIN# (Serial Data In)
3	SOUT# (Serial Data Out)
4	DTR (Data Terminal Ready)
5	Ground
6	DSR (Data Set Ready)
7	RTS (Request to Send)
8	CTS (Clear to Send)
9	RI (Ring Indicator)

Table 23. MIDI/Game Port Connector

Pin	Signal Name	Pin	Signal Name
1	+5 V (fused)	9	+5 V (fused)
2	GP4 (JSBUT0)	10	GP6 (JSBUT2)
3	GP0 (JSX1)	11	GP2 (JSX2)
4	Ground	12	MIDI-OUT
5	Ground	13	GP3 (JSY2)
6	GP1 (JSY1)	14	GP7 (JSBUT3)
7	GP5 (JSBUT1)	15	MIDI-IN
8	+5 V (fused)		

Table 24. Audio Line Out Connector

Pin	Signal
Tip	Audio left out
Ring	Audio right out
Sleeve	Ground

Table 25. Audio Line In Connector

Pin	Signal
Tip	Audio left in
Ring	Audio right in
Sleeve	Ground

Table 26. Audio Mic In Connector

Pin	Signal
Tip	Mono in
Ring	Mic bias voltage
Sleeve	Ground

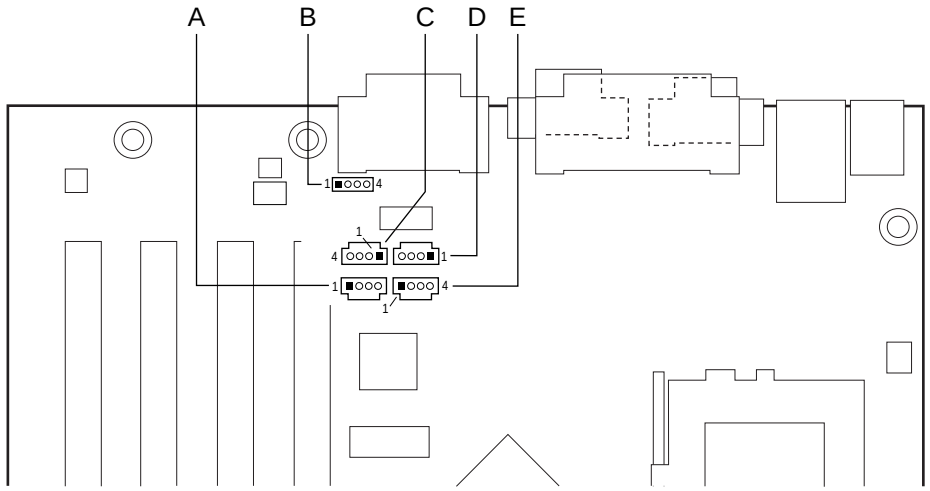
2.8.2 Midboard Connectors

The midboard connectors are divided into the following functional groups:

- Audio (see page 52)
  - ATAPI-style CD-ROM
  - Legacy-style CD-ROM
  - Video source line in (optional)
  - Auxiliary line in (optional)
  - Telephony (optional)
- Peripheral interfaces (see page 54)
  - Serial port B
  - IDE (2)
  - Diskette drive
  - USB front panel (optional)
- Hardware Management and Power (see page 57)
  - Fans (3)
  - Power
  - Wake on LAN technology connector
  - Chassis intrusion (optional)
- PCI bus connectors (see page 59)

2.8.2.1 Audio

Figure 8 shows the location of the audio connectors.



Item	Description	Color	Style	Reference Designator
A	CD-ROM	black	ATAPI	J2C2
B	CD-ROM (optional)	white	Legacy, 2 mm	J1C1
C	Video source line in (optional)	blue	ATAPI	J2C1
D	Auxiliary line in (optional)	natural	ATAPI	J2D2
E	Telephony (optional)	green	ATAPI	J2D3

Figure 8. Midboard Audio Connectors

Table 27. ATAPI CD-ROM Connector (J2C2)

Pin	Signal
1	Left audio input from CD-ROM
2	CD audio differential ground
3	CD audio differential ground
4	Right audio input from CD-ROM

Table 28. Legacy CD-ROM Connector (J1C1)

Pin	Signal
1	CD audio differential ground
2	Left audio input from CD-ROM
3	CD audio differential ground
4	Right audio input from CD-ROM

Table 29. Optional Video Source Line In Connector (J2C1)

Pin	Signal
1	Left auxiliary line in
2	Ground
3	Ground
4	Right auxiliary line in

Table 30. Optional Auxiliary Line In Connector (J2D2)

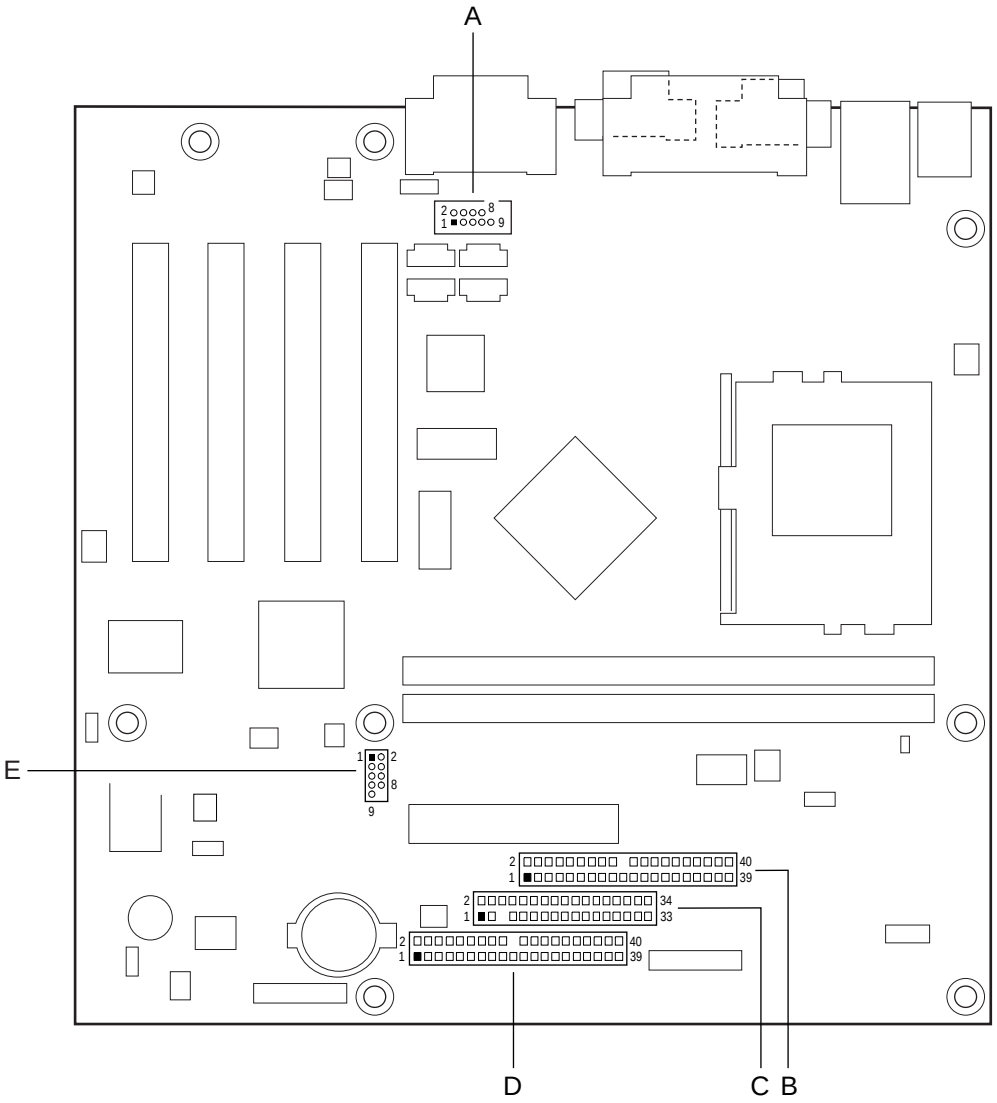
Pin	Signal
1	Left auxiliary line in
2	Ground
3	Ground
4	Right auxiliary line in

Table 31. Optional Telephony Connector (J2D3)

Pin	Signal
1	Analog audio mono input
2	Ground
3	Ground
4	Analog audio mono output

2.8.2.2 Peripheral Interfaces

Figure 9 shows the location of the peripheral interface connectors.



Item	Description	Reference Designator
A	Serial port B	J2D1
B	Secondary IDE	J9F1
C	Diskette drive	J9E1
D	Primary IDE	J9D1
E	USB front panel (optional)	J8C1

Figure 9. Peripheral Interface Connectors

Table 32. Serial Port B Connector (J2D1)

Pin	Signal	Pin	Signal
1	DCD (Data Carrier Detect)	2	DSR (Data Set Ready)
3	SIN# (Serial Data In)	4	RTS (Request to Send)
5	SOUT# (Serial Data Out)	6	CTS (Clear to Send)
7	DTR (Data Terminal Ready)	8	RI (Ring Indicator)
9	Ground		

Table 33. PCI IDE Connectors (J9D1, J9F1)

Pin	Signal	Pin	Signal
1	Reset IDE	2	Ground
3	Data 7	4	Data 8
5	Data 6	6	Data 9
7	Data 5	8	Data 10
9	Data 4	10	Data 11
11	Data 3	12	Data 12
13	Data 2	14	Data 13
15	Data 1	16	Data 14
17	Data 0	18	Data 15
19	Ground	20	Key
21	DDRQ0 [DDRQ1]	22	Ground
23	I/O Write#	24	Ground
25	I/O Read#	26	Ground
27	IOCHRDY	28	P_ALE (Cable Select pull-up)
29	DDACK0# [DDACK1#]	30	Ground
31	IRQ 14 [IRQ 15]	32	Reserved
33	DAG1 (Address 1)	34	Reserved
35	DAG0 (Address 0)	36	DAG2Address 2
37	Chip Select 1P# [Chip Select 1S#]	38	Chip Select 3P# [Chip Select 3S#]
39	Activity#	40	Ground

NOTE: Signal names in brackets ([ ]) are for the secondary IDE connector.

Table 34. Diskette Drive Connector (J9E1)

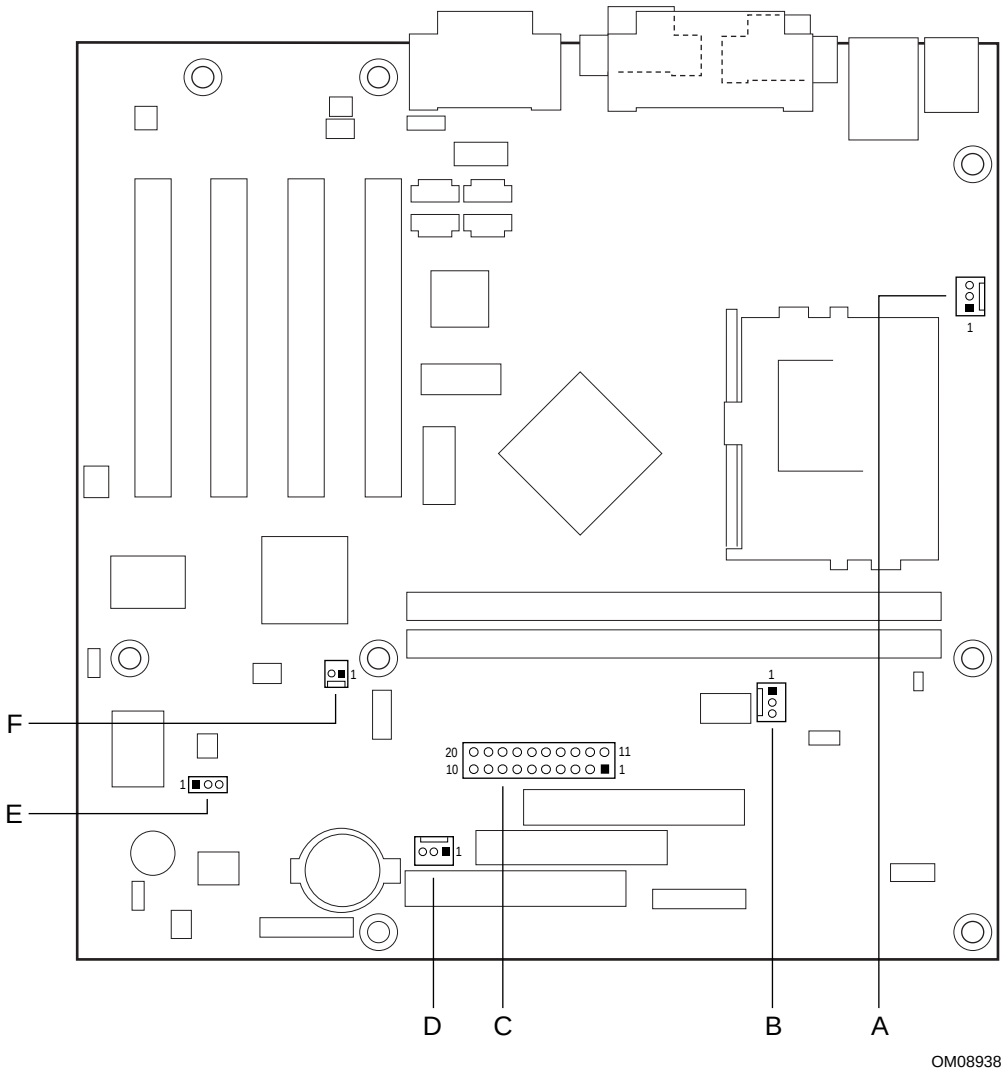
Pin	Signal	Pin	Signal
1	Ground	2	DENSEL
3	Ground	4	Reserved
5	Key	6	FDEDIN
7	Ground	8	FDINDX# (Index)
9	Ground	10	FDM00# (Motor Enable A)
11	Ground	12	No connect
13	Ground	14	FDDS0# (Drive Select A)
15	Ground	16	No connect
17	No connect	18	FDDIR# (Stepper Motor Direction)
19	Ground	20	FDSTEP# (Step Pulse)
21	Ground	22	FDWD# (Write Data)
23	Ground	24	FDWE# (Write Enable)
25	Ground	26	FDTRK0# (Track 0)
27	No connect	28	FDWPD# (Write Protect)
29	Ground	30	FDRDATA# (Read Data)
31	Ground	32	FDHEAD# (Side 1 Select)
33	Ground	34	DSKCHG# (Diskette Change)

Table 35. Optional USB Front Panel Connector (J8C1)

Pin	Signal	Pin	Signal
1	TP_FPUSB_1	2	VCC
3	Ground	4	TP_FUSB_4
5	TP_FPUSB_5	6	FNT_USBP0
7	Ground	8	FNT_USBP0 #
9	Ground		

2.8.2.3 Hardware Management and Power

Figure 10 shows the location of the hardware management and power connectors.



Item	Description	Reference Designator
A	Fan 3 (optional)	J3J1
B	Fan 2 (processor)	J7G1
C	Power	J8D1
D	Fan 1 (chassis)	J9C1
E	Wake on LAN technology connector	J8A3
F	Chassis Intrusion (optional)	J7B1

Figure 10. Hardware Management and Power Connectors

Table 36. Optional Fan 3 Connector (J3J1)

Pin	Signal
1	Ground
2	+12 V
3	Ground

Table 37. Fan 2 (Processor) Connector (J7G1)

Pin	Signal
1	Ground
2	+12 V (FAN_C)
3	Tach

Table 38. Power Connector (J8D1)

Pin	Signal	Pin	Signal
1	+3.3 V	11	+3.3 V
2	+3.3 V	12	-12 V
3	Ground	13	Ground
4	+5 V	14	PS-ON# (power supply remote on/off)
5	Ground	15	Ground
6	+5 V	16	Ground
7	Ground	17	Ground
8	PWRGD (Power Good)	18	-5 V
9	+5 VSB	19	+5 V
10	+12 V	20	+5 V

NOTE

The standard SFX 90 W power supply is not sufficient for the CA810E board. For more information, see Power Consumption on page 67.

Table 39. Fan 1 (Chassis) Connector (J9C1)

Pin	Signal
1	Ground
2	+12 V (FAN_C)
3	Tach

Table 40. Wake on LAN Technology Connector (J8A3)

Pin	Signal
1	+5 VSB
2	Ground
3	WOL

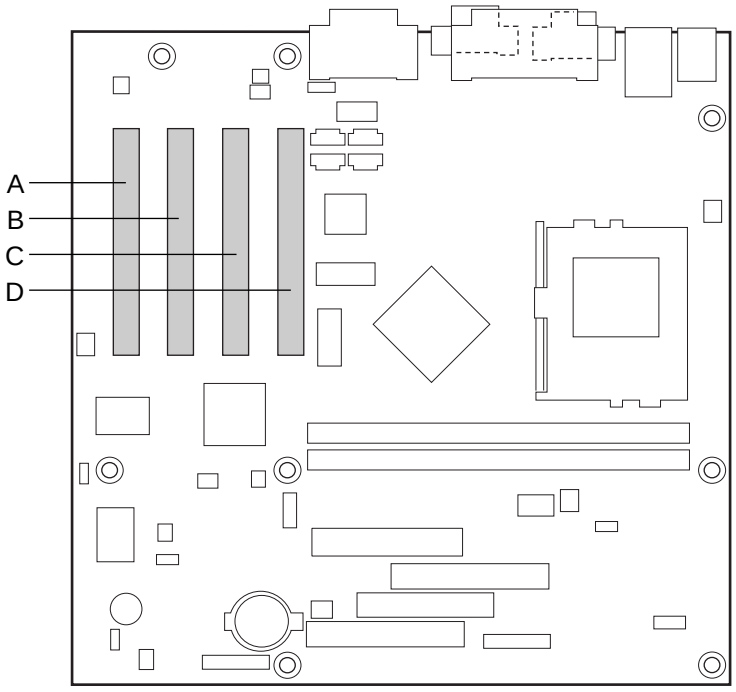
Table 41. Optional Chassis Intrusion Connector (J7B1)

Pin	Signal
1	CHS_SECURITY
2	Ground

2.8.2.4 PCI Bus Connectors

Figure 11 shows the location of the PCI bus connectors. Note the following considerations for the connectors:

- All of the PCI bus connectors are bus master capable.
- PCI bus connector 2 has optional SMBus signals routed to it. This enables PCI bus add-in boards with SMBus support to access sensor data on the board. The specific SMBus signals are as follows:
  - The SMBus clock line is connected to pin A40
  - The SMBus data line is connected to pin A41



Item	Description	Reference Designator
A	PCI bus connector 4	J4A1
B	PCI bus connector 3	J4A2
C	PCI bus connector 2	J4B1
D	PCI bus connector 1	J4C1

Figure 11. PCI Bus Add-In Board Connectors

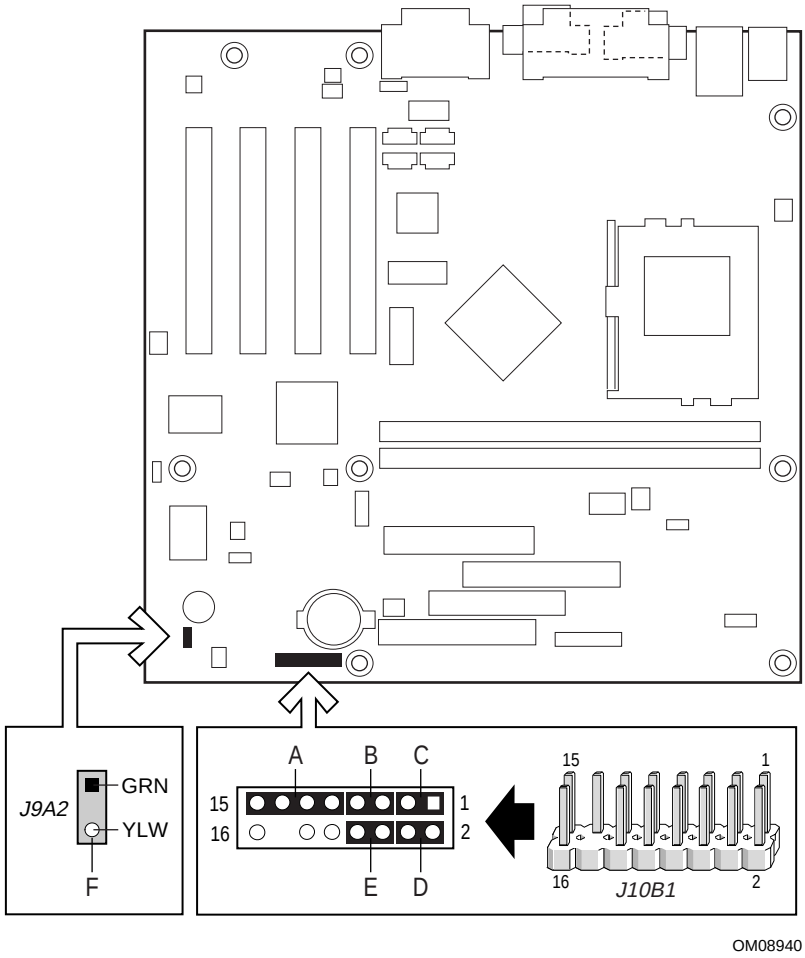
Table 42. PCI Bus Connectors

Pin	Signal	Pin	Signal	Pin	Signal	Pin	Signal
A1	Ground (TRST#)*	B1	-12 V	A32	AD16	B32	AD17
A2	+12 V	B2	Ground (TCK)*	A33	+3.3 V	B33	C/BE2#
A3	+5 V (TMS)*	B3	Ground	A34	FRAME#	B34	Ground
A4	+5 V (TDI)*	B4	no connect (TDO)*	A35	Ground	B35	IRDY#
A5	+5 V	B5	+5 V	A36	TRDY#	B36	+3.3 V
A6	INTA#	B6	+5 V	A37	Ground	B37	DEVSEL#
A7	INTC#	B7	INTB#	A38	STOP#	B38	Ground
A8	+5 V	B8	INTD#	A39	+3.3 V	B39	LOCK#
A9	Reserved	B9	no connect (PRSNT1#)*	A40	Reserved**	B40	PERR#
A10	+5 V (I/O)	B10	Reserved	A41	Reserved***	B41	+3.3 V
A11	Reserved	B11	no connect (PRSNT2#)*	A42	Ground	B42	SERR#
A12	Ground	B12	Ground	A43	PAR	B43	+3.3 V
A13	Ground	B13	Ground	A44	AD15	B44	C/BE1#
A14	+3.3 V aux	B14	Reserved	A45	+3.3 V	B45	AD14
A15	RST#	B15	Ground	A46	AD13	B46	Ground
A16	+5 V (I/O)	B16	CLK	A47	AD11	B47	AD12
A17	GNT#	B17	Ground	A48	Ground	B48	AD10
A18	Ground	B18	REQ#	A49	AD09	B49	Ground
A19	PME#	B19	+5 V (I/O)	A50	Key	B50	Key
A20	AD30	B20	AD31	A51	Key	B51	Key
A21	+3.3 V	B21	AD29	A52	C/BE0#	B52	AD08
A22	AD28	B22	Ground	A53	+3.3 V	B53	AD07
A23	AD26	B23	AD27	A54	AD06	B54	+3.3 V
A24	Ground	B24	AD25	A55	AD04	B55	AD05
A25	AD24	B25	+3.3 V	A56	Ground	B56	AD03
A26	IDSEL	B26	C/BE3#	A57	AD02	B57	Ground
A27	+3.3 V	B27	AD23	A58	AD00	B58	AD01
A28	AD22	B28	Ground	A59	+5 V (I/O)	B59	+5 V (I/O)
A29	AD20	B29	AD21	A60	REQ64C#	B60	ACK64C#
A30	Ground	B30	AD19	A61	+5 V	B61	+5 V
A31	AD18	B31	+3.3 V	A62	+5 V	B62	+5 V

* These signals (in parentheses) are optional in the PCI specification and are not currently implemented.
** On PCI bus connector 2, this pin is connected to the optional SMBus clock line.
*** On PCI bus connector 2, this pin is connected to the optional SMBus data line.

2.8.3 Front Panel Connectors

Figure 12 shows the location of the front panel connectors, and Table 43 lists the connector signals.



A	Infrared Port	D	Power LED
B	Reset Switch	E	On/Off Switch
C	Hard Drive Activity LED	F	Power LED

Figure 12. Front Panel Connectors

Table 43. Front Panel Connector (J10B1)

Pin	Signal	In/Out	Description	Pin	Signal	In/Out	Description
Hard Drive Activity LED				Power LED			
1	HD_PWR	Out	Hard disk LED pull-up (330 Ω) to +5 V	2	HDR_BLNK_GRN	Out	Front panel green LED
3	HDA#	Out	Hard disk active LED	4	HDR_BLNK_YEL	Out	Front panel yellow LED
Reset Switch				On / Off Switch			
5	GND		Ground	6	FPBUT_IN	In	Front panel On/Off button
7	FP_RESET#	In	Front panel Reset button	8	GND		Ground
Infrared Port				Miscellaneous			
9	+5 V	Out	IR Power	10	N/C	In	Not connected
11	IRRX	In	IrDA serial input	12	GND		Ground
13	GND		Ground	14	(Pin removed)		Not connected
15	IRTX	Out	IrDA serial output	16	+5 V	Out	Power

2.8.3.1 Power / Sleep / Message Waiting LED Connector

Pins 2 and 4 can be connected to either a single or dual colored LED that will light when the computer is powered on. Table 44 shows the possible states for a single-colored LED.

Table 45 shows the possible states for a dual-colored LED.

Table 44. States for a Single-colored Power LED

LED State	Description	ACPI State
Off	Off	S1, S3, S5
Steady Green	Running	S0
Blinking Green	Running / message waiting	S0

Table 45. States for a Dual-colored Power LED

LED State	Description	ACPI State
Off	Off	S5
Steady Green	Running	S0
Blinking Green	Running / message waiting	S0
Steady Yellow	Sleeping	S1, S3
Blinking Yellow	Sleeping / message waiting	S1, S3

NOTE

To use the message waiting function, ACPI must be enabled in the operating system and a message-capturing application must be invoked.

2.8.3.2 Power Switch Connector

Pins 6 and 8 can be connected to a front panel power switch. The switch must pull pin 6 to ground for at least 50 ms to signal the power supply to switch on or off. (The time requirement is due to internal debounce circuitry on the board.) At least two seconds must pass before the power supply will recognize another on/off signal.

2.8.3.3 Hard Drive Activity LED connector

Pins 1 and 3 can be connected to an LED to provide a visual indicator that data is being read from or written to a hard drive. For the LED to function properly, an IDE drive must be connected to the onboard hard drive controller.

2.8.3.4 Reset Switch Connector

Pins 5 and 7 can be connected to a momentary SPST type switch that is normally open. When the switch is closed, the board resets and runs the POST.

2.8.3.5 Infrared Port Connector

Pins 9, 11, 13, and 15 can be connected to an IrDA module. After the IrDA interface is configured, files can be transferred to or from portable devices such as laptops, PDAs, and printers using application software.

2.8.3.6 Power LED Connector (J9A2)

Table 46 lists the signals for the power LED front panel connector.

Table 46. Power LED Front Panel Connector (J9A2)

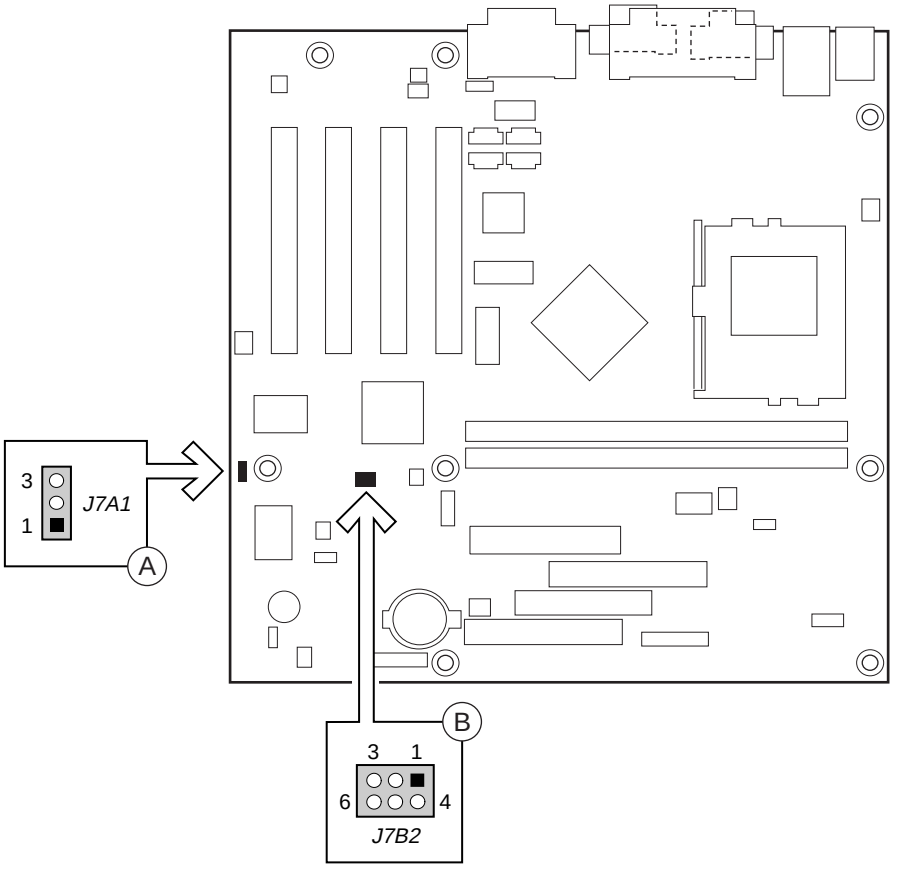
Pin	Signal	In/Out	Description
1	HDR_BLNK_GRN	Out	Front panel green LED
2			Not connected
3	HDR_BLNK_YEL	Out	Front panel yellow LED

2.9 Jumper Blocks

Figure 13 shows the location of the board's jumper blocks.

CAUTION

Do not move the jumper with the power on. Always turn off the power and unplug the power cord from the computer before changing the jumper. Otherwise, the board could be damaged.



A BIOS setup configuration jumper block
B USB port 0 configuration jumper block (optional)

Figure 13. Location of the Jumper Blocks

2.9.1 BIOS Setup Configuration Jumper Block

This 3-pin jumper block enables all board configuration to be done in BIOS Setup. Table 47 describes the jumper settings for normal, configure, and recovery modes.

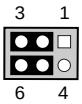
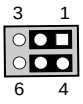
Table 47. BIOS Setup Configuration Jumper Settings

Function / Mode	Jumper Setting	Configuration
Normal	1-2 	The BIOS uses current configuration information and passwords for booting.
Configure	2-3 	After the POST runs, Setup runs automatically. The maintenance menu is displayed.
Recovery	None 	The BIOS attempts to recover the BIOS configuration. A recovery medium is required.

2.9.2 USB Port 0 Configuration Jumper Block (Optional)

This 6-pin jumper block allows rerouting of USB Port 0. Table 48 describes the jumper settings.

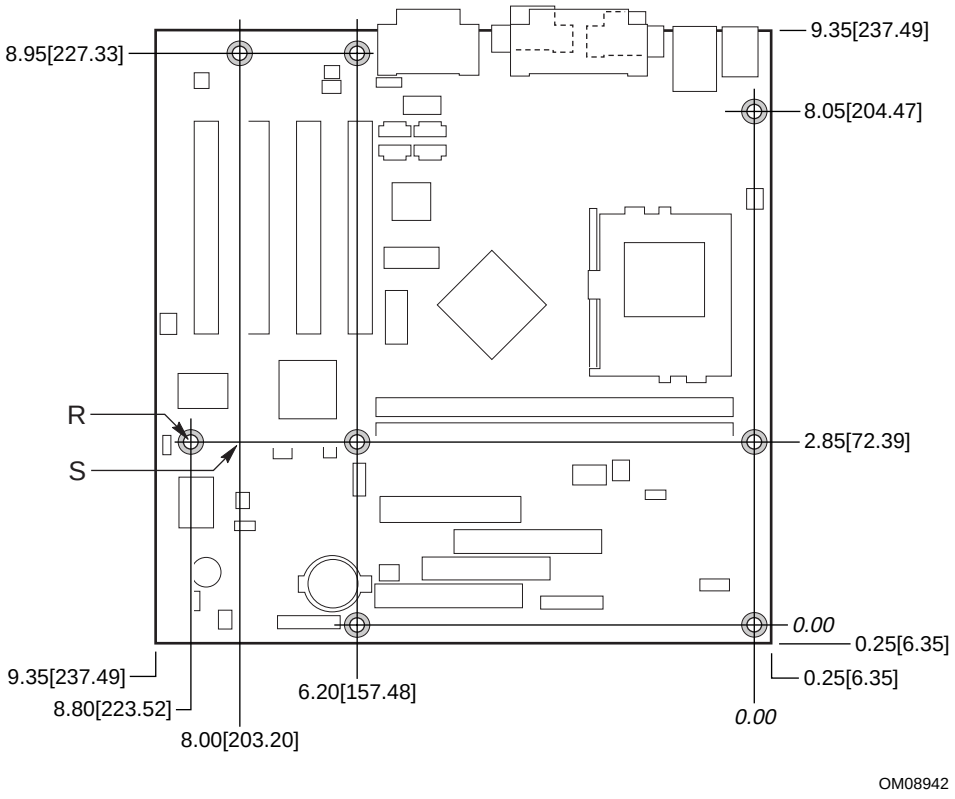
Table 48. USB Port 0 Configuration Jumper Settings

Jumper Setting	Configuration
2-3 and 5-6 	USB Port 0 signals are routed to the back panel.
1-2 and 4-5 	USB Port 0 signals are routed for a front panel USB connector.

2.10 Mechanical Considerations

2.10.1 Form Factor

The board is designed to fit into a microATX or a standard ATX form factor chassis. Figure 14 illustrates the mechanical form factor for the board. Dimensions are given in inches and [millimeters]. The outer dimensions are 9.6 x 9.6 inches [243.84 x 243.84 millimeters]. Location of the I/O connectors and mounting holes are in strict compliance with the microATX specification (see Section 1.3).



R New mounting hole for microATX desktop boards

S Optional mounting hole

Figure 14. Board Dimensions

⚠ **CAUTION**

As permitted by the microATX specification, the optional hole at location S in Figure 14 was omitted from the CA810E board. The chassis standoff in this position should not be implemented or should be removable to avoid damage to traces on the board.

2.10.2 I/O Shield

The back panel I/O shield for the board must meet specific dimension and material requirements. Systems based on this board need the back panel I/O shield to pass certification testing. Figure 15 shows the critical dimensions of the chassis-independent I/O shield. Dimensions are given in millimeters and [inches]. The figure indicates the position of each cutout. Additional design considerations for I/O shields relative to chassis requirements are described in the microATX specification.

NOTE

A chassis-independent I/O shield designed to be compliant with the microATX chassis specification is available from Intel. The actual punchouts may differ depending on the board manufacturing options.

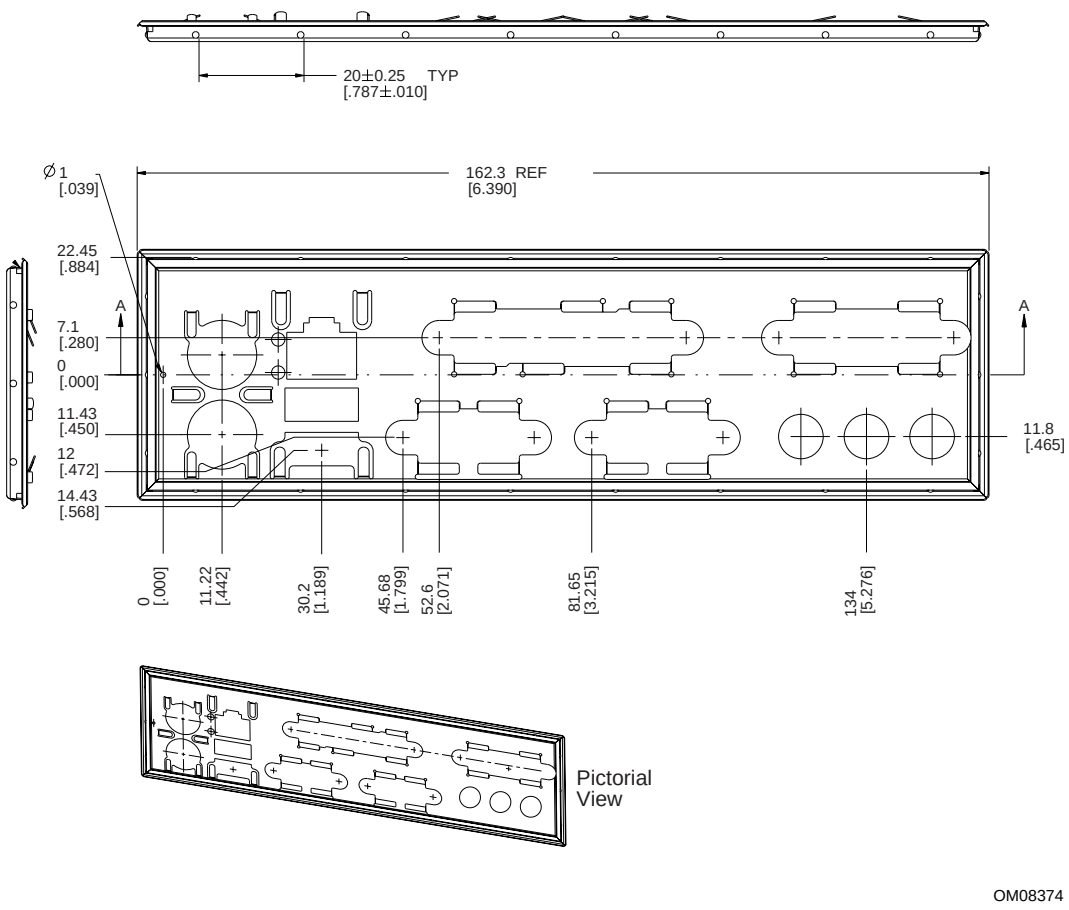


Figure 15. Back Panel I/O Shield Dimensions (microATX Chassis - Independent)

2.11 Electrical Considerations

2.11.1 Power Consumption

Table 49 lists typical power usage measurements. These figures are provided to assist in selecting appropriate desktop power supplies for the CA810E board. Power usage measurements will vary depending upon actual system configurations.

The power measurements listed in Table 49 were made with a desktop computer containing the CA810E board and the following:

- 533 MHz Intel Celeron processor with a 128 KB cache
- 96 MB SDRAM
- 3.5-inch diskette drive
- 8.4 GB IDE hard disk drive
- IDE CD-ROM drive
- IDE DVD drive

This information is provided only as a guide for calculating approximate power usage with additional resources added.

Values for the Windows 98 desktop mode are measured at 640 x 480 x 256 colors and 60 Hz refresh rate. AC watts are measured with a typical 200 W supply, nominal input voltage and frequency, with a true RMS wattmeter at the line input.

NOTE

Actual system power consumption depends upon system configuration. The power supply should comply with the recommendations found in the ATX form factor.

Table 49. Typical Power Usage

Power Management Mode	Windows 98 APM Full on (idle)	Windows 98 APM Suspend	Windows 98 ACPI S0 (Idle)	Windows 98 ACPI S1	Windows 98 ACPI S3	Windows 98 ACPI S5
Power Supply AC Watts (without onboard LAN)	60 W	29 W	58 W	29 W	3 W	1 W
Power Supply AC Watts (with onboard LAN)	61 W	30 W	58 W	29 W	3 W	1 W

Table 50 lists the maximum current needed for each power supply voltage. Although not seen continuously, these peak values may occur during normal operation. Power supplies chosen for the CA810E board should be able to meet the maximum power supply current requirements, plus any additional system and add-in board requirements.

Table 50. Power Supply Current Requirements (Full on at Idle)

DC Voltage	+3.3 V	+5 V	+12 V	-12 V	+5 VSB
Nominal Current (measured without onboard LAN)	0.37 A	0.14 A	0.13 A	0.01 A	0.13 A
Nominal Current (measured with onboard LAN)	0.39 A	0.12 A	0.14 A	0	0.21 A

2.11.2 Add-in Board Considerations

The board is designed to provide 2 A (average) of +5 V current for each add-in board. The total +5 V current draw for add-in boards in a fully-loaded board (all four expansion slots filled) must not exceed 8 A.

2.11.3 Standby Current Requirements

⚠ CAUTION

If the standby current necessary to support multiple wake events from the PCI and/or USB buses exceeds power supply capacity, the CA810E board may lose register settings stored in memory, etc. Calculate the standby current requirements using the steps described below.

Power supplies used with the CA810E board must be able to provide enough standby current to support the Instantly Available (ACPI S3 sleep state) configuration as outlined in Table 51 below.

Values are determined by specifications such as PCI 2.2. Actual measured values may vary.

To estimate the amount of standby current required for a particular system configuration, standby current requirements of all installed components must be added to determine the total standby current requirement. Refer to the descriptions in Table 51 below and review the following steps:

1. Note the total CA810E desktop board standby current requirement.
2. Add the PCI 2.2 slots with wake enabled devices installed and multiply by the standby current requirement for wake enabled devices.
3. Add the PCI 2.2 slots with wake enabled devices installed, and multiply by the standby current requirement for non-wake enabled devices.
4. Add all additional wake enabled devices' and non-wake enabled devices' standby current requirements as applicable.
5. Add all the required current totals from steps 1 through 4 to determine the total estimated standby current power supply requirement.

Table 51. Standby Current Requirements

Instantly Available Current Support (Estimated for integrated board components)	Description	Standby Current Requirements (mA)
	Total for the CA810E board	200 (with onboard LAN)
Instantly Available Stand-by Current Support • **Estimated for add-on components** • **Add to Instantly Available total current requirement** **(See instructions above)**	PCI 2.2 slots (wake enabled)	375
	PCI 2.2 slots (non-wake enabled)	20
	Wake on LAN technology header	225

NOTE

IBM PS/2 Port Specification (Sept 1991) states

- *275 mA for keyboard*
- *70 mA for the mouse (not wake-enable device)*

PCI requirements are calculated by totaling the following:

- *One wake-enabled device @ 375 mA*
- *Non wake-enabled devices @ 20 mA each*

2.11.4 Fan Power Requirements

The CA810E board is capable of supplying 250 mA per fan connector (maximum).

2.11.5 Power Supply Considerations

CAUTION

The 5-V standby line for the power supply must be capable of providing adequate +5 V standby current. Failure to do so can damage the power supply. The total amount of standby current required depends on the wake devices supported and manufacturing options. Refer to Section 2.11.3 on page 68 for additional information.

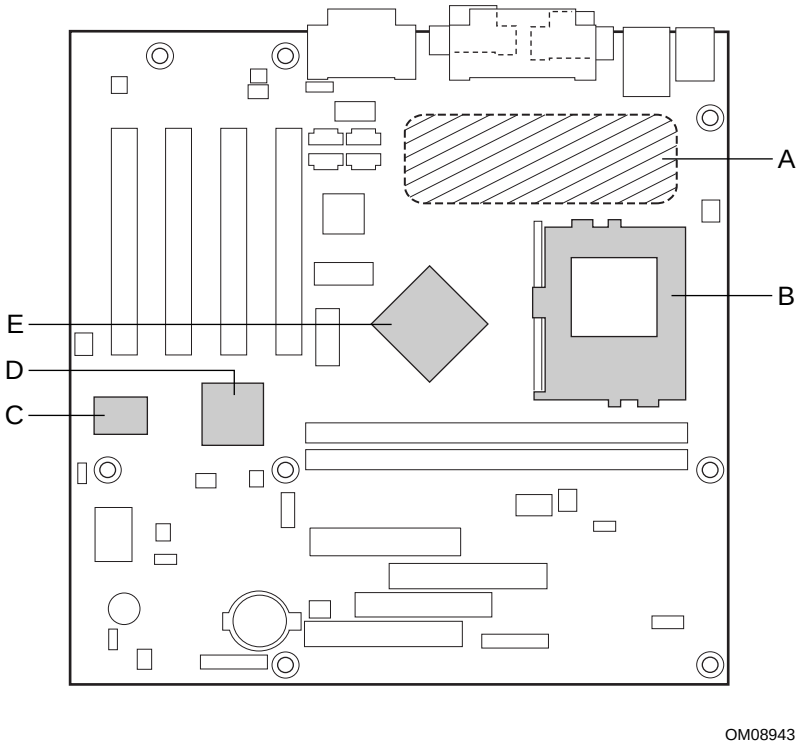
System integrators should refer to the power usage values listed in Table 49 and Table 50 when selecting a power supply for use with this board. The power supply must comply with the following recommendations found in the indicated sections of the ATX form factor specification.

- The potential relation between 3.3 VDC and +5 VDC power rails (Section 4.2)
- The current capability of the +5 VSB line (Section 4.2.2.2)
- All timing parameters (Section 4.2.2.3)
- All voltage tolerances (Section 4.2.3)

For information about	Refer to
The ATX form factor specification	Section 1.3, page 16

2.12 Thermal Considerations

Figure 16 shows the locations where heat dissipation is of maximum concern. Table 52 provides maximum component case temperatures for board components that could be sensitive to thermal changes. Case temperatures could be affected by the operating temperature, current load, or operating frequency. Maximum case temperatures are important when considering proper airflow to cool the board.



A	Voltage regulator area
B	PGA370 processor
C	Creative ES1373 audio controller
D	Intel 82801AA ICH
E	Intel 82810E GMCH

Figure 16. High-Temperature Zones

NOTE

The voltage regulator (VREG) area can heat up to 85 °C in an open chassis. The chassis should have proper airflow.

CAUTION

An ambient temperature that exceeds the board's maximum operating temperature by 5 °C to 10 °C could cause components to exceed their maximum case temperature and malfunction. For information about the maximum operating temperature, see the environmental specifications in Section 2.14.

Table 52. Thermal Considerations for Components

Component	Maximum Case Temperature	
Intel Pentium III processor	500E	85 °C (case)
	550E	85 °C (case)
Intel Celeron processor	333 MHz	85 °C (case)
	366 MHz	85 °C (case)
	400 MHz	85 °C (case)
	433 MHz	85 °C (case)
	466 MHz	85 °C (case)
	500 MHz	85 °C (case)
Intel 82810E DC-133 GMCH	70 °C	
Intel 82801AA ICH	100 °C	
Creative ES1373 audio controller	70 °C	
VREG area	70 °C - 85 °C	

2.13 Reliability

The mean time between failures (MTBF) prediction is calculated using component and subassembly random failure rates. The calculation is based on the Bellcore Reliability Prediction Procedure, TR-NWT-000332, Issue 4, September 1991. The MTBF prediction is for estimating repair rates and spare parts requirements.

The Mean Time Between Failures (MTBF) data is calculated from predicted data at 35 ºC.

Board MTBF: 478,832 hours

2.14 Environmental Specifications

Table 53. Environmental Specifications

Parameter	Specification		
Temperature			
Nonoperating	-40 °C to +70 °C		
Operating	0 °C to +55 °C		
Shock			
Unpackaged	30 g trapezoidal waveform		
	Velocity change of 170 inches/sec		
Packaged	Half sine 2 millisecond		
	Product Weight (lbs)	**Free Fall (inches)**	**Velocity Change (inches/sec)**
	<20	36	167
	21-40	30	152
	41-80	24	136
	81-100	18	118
Vibration			
Unpackaged	5 Hz to 20 Hz : 0.01 g² Hz sloping up to 0.02 g² Hz		
	20 Hz to 500 Hz : 0.02 g² Hz (flat)		
Packaged	10 Hz to 40 Hz : 0.015 g² Hz (flat)		
	40 Hz to 500 Hz : 0.015 g² Hz sloping down to 0.00015 g² Hz		

2.15 Regulatory Compliance

This board complies with the following safety and EMC regulations when correctly installed in a compatible host system.

2.15.1 Safety Regulations

Table 54 lists the safety regulations the board complies with when it is correctly installed in a compatible host system.

Table 54. Safety Regulations

Regulation	Title
UL 1950/CSA950, 3rd edition, Dated 07-28-95	Bi-National Standard for Safety of Information Technology Equipment including Electrical Business Equipment. (USA and Canada)
EN 60950, 2nd Edition, 1992 (with Amendments 1, 2, 3, and 4)	The Standard for Safety of Information Technology Equipment including Electrical Business Equipment. (European Community)
IEC 950, 2nd edition, 1991 (with Amendments 1, 2, 3, and 4)	The Standard for Safety of Information Technology Equipment including Electrical Business Equipment. (International)
EMKO-TSE (74-SEC) 207/94	Summary of Nordic deviations to EN 60950. (Norway, Sweden, Denmark, and Finland)

2.15.2 Safety Regulations

Table 55 lists the EMC regulations the board complies with when it is correctly installed in a compatible host system.

Table 55. EMC Regulations

Regulation	Title
FCC Class B	Title 47 of the Code of Federal Regulations, Parts 2 and 15, Subpart B, pertaining to unintentional radiators. (USA)
CISPR 22, 2nd Edition, 1993 (Class B)	Limits and methods of measurement of Radio Interference Characteristics of Information Technology Equipment. (International)
VCCI Class B (ITE)	Implementation Regulations for Voluntary Control of Radio Interference by Data Processing Equipment and Electronic Office Machines. (Japan)
EN55022 (1994) (Class B)	Limits and methods of measurement of Radio Interference Characteristics of Information Technology Equipment. (Europe)
EN50082-1 (1992)	Generic Immunity Standard; Currently compliance is determined via testing to IEC 801-2, -3, and -4. (Europe)
ICES-003 (1997)	Interference-Causing Equipment Standard, Digital Apparatus, Class B (Including CRC c.1374). (Canada)
AS/NZ 3548	Australian Communications Authority (ACA), Standard for Electromagnetic Compatibility.

2.15.3 Certification Markings

This printed circuit assembly has the following product certification markings:

- UL Joint Recognition Mark: Consists of small c followed by a stylized backward UR and followed by a small US (Component side)
- Manufacturer's recognition mark: Consists of a unique UL recognized manufacturer's logo, along with a flammability rating (94V-0) (Solder side)
- UL File Number for boards: E139761 (Component side)
- PB Part Number: Intel bare circuit board part number A02456-001 (Solder side)
- Battery "+ Side Up" marking: located on the component side of the board in close proximity to the battery holder
- FCC Logo/Declaration: (Solder side)
- ACA (C-Tick) mark: Consists of a unique letter C, with a tick mark; followed by N-232. Located on the component side of the board and on the shipping container.
- CE Mark: (Component side) The CE mark should also be on the shipping container

3 Overview of BIOS Features

What This Chapter Contains

3.1 Introduction

The CA810E board uses an Intel/AMI BIOS, which is stored in flash memory and can be upgraded using a disk-based program. In addition to the BIOS, the flash memory contains the BIOS Setup program, POST, APM, ACPI, PCI auto-configuration utility, and Windows 98-ready Plug and Play.

This board supports system BIOS shadowing, allowing the BIOS to execute from 64-bit onboard write-protected DRAM.

The BIOS displays a message during POST identifying the type of BIOS and a revision code. The initial production BIOS is identified as CA81020A.86A.

For information about	Refer to
The CA810E board's compliance level with APM, ACPI, and Plug and Play	Section 1.3, page 16

3.2 BIOS Flash Memory Organization

The Intel 82802AB Firmware Hub (FWH) is a high performance 4 Mbit (512 KB) symmetrical flash memory device. Internally, the device is grouped into eight 64-KB blocks that are individually erasable, lockable, and unlockable. Figure 17 shows the organization of the flash memory.

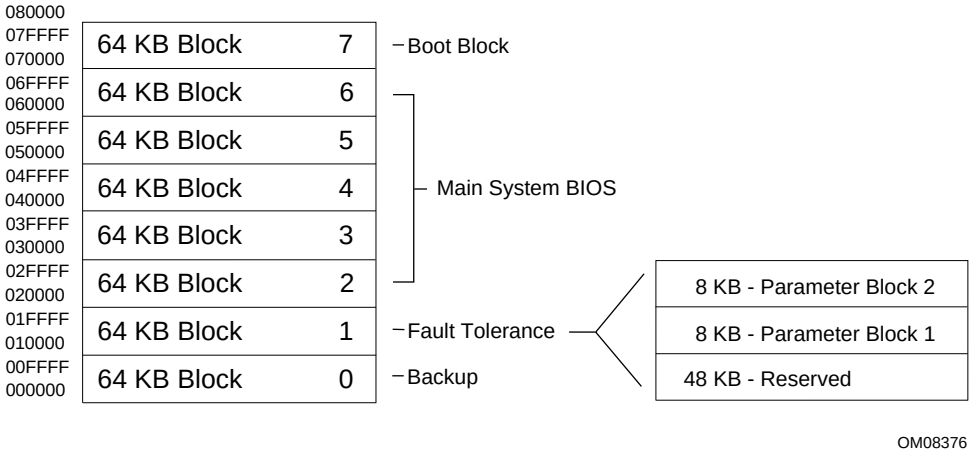


Figure 17. Memory Map of the Flash Memory Device

Symmetrical flash memory allows both the boot and the fault tolerance blocks to increase in size from 16 KB to 64 KB. This increase allows the addition of features such as dynamic memory detection, LS-120 recovery code, and extended security features.

The last two 8 KB blocks of the fault tolerance area are the parameter blocks. These blocks contain data such as BIOS updates, vital product data (VPD), logo, System Management BIOS (SMBIOS) interface, and extended system configuration data (ESCD) information. The backup block contains a copy of the fault tolerance block.

3.3 Resource Configuration

3.3.1 PCI Autoconfiguration

The BIOS can automatically configure PCI devices. PCI devices may be onboard or add-in cards. Autoconfiguration lets a user insert or remove PCI cards without having to configure the system. When a user turns on the system after adding a PCI card, the BIOS automatically configures interrupts, the I/O space, and other system resources. PCI devices can share an interrupt. Auto configuration information is stored in ESDC format.

For information about the versions of PCI supported by this BIOS, see Section 1.3.

3.3.2 PCI IDE Support

If the user selects Auto in Setup (see Section 4.4.4.1), the BIOS automatically sets up the two PCI IDE connectors with independent I/O channel support. The IDE interface supports hard drives up to PIO Mode 4 and recognizes any ATAPI devices, including CD-ROM drives, tape drives, and Ultra DMA drives (see Table 3 on page 16 for the supported version of ATAPI). The BIOS determines the capabilities of each drive and configures them to optimize capacity and performance. You can override the autoconfiguration option by specifying User configuration in the IDE configuration Submenu of the BIOS Setup program (see Section 4.4.4.1 on page 93).

To use the ATA-66 functionality, the following items are required:

- An ATA-66 peripheral device
- An ATA-66 compatible cable
- ATA-66 operating system device drivers

NOTE

ATA-66 compatible cables are backward compatible with drives using slower IDE transfer protocols. If an Ultra ATA/66 drive and a drive using any other IDE transfer protocol are attached to the same cable, the maximum transfer rate for either drive is 33 MB/second.

NOTE

Do not connect an ATA device as a slave on the same IDE cable as an ATAPI master device. For example, do not connect an ATA hard drive as a slave to an ATAPI CD-ROM drive.

3.4 System Management BIOS (SMBIOS)

SMBIOS is an interface for managing computers in an enterprise environment.

The main component of SMBIOS is the management information format (MIF) database, which contains information about the computing system and its components. Using SMBIOS, a system administrator can obtain the system types, capabilities, operational status, and installation dates for system components. The MIF database defines the data and provides the method for accessing this information. The BIOS enables applications such as Intel® LANDesk® Client Manager to use SMBIOS. The BIOS stores and reports the following SMBIOS information:

- BIOS data, such as the BIOS revision level
- Fixed-system data, such as peripherals, serial numbers, and asset tags
- Resource data, such as memory size, cache size, and processor speed
- Dynamic data, such as event detection and error logging

Non-Plug and Play operating systems, such as Windows NT†, require an additional interface for obtaining SMBIOS information. The BIOS supports an SMBIOS table interface for such operating systems. Using this support, a SMBIOS service-level application running on a non-Plug and Play operating system can access the SMBIOS BIOS information.

For information about	Refer to
The CA810E board's compliance level with SMBIOS	Section 1.3, page 16

3.5 BIOS Upgrades

A new version of the BIOS can be upgraded from a diskette using the Intel® Flash Memory Update Utility that is available from Intel. This utility supports the following BIOS maintenance functions:

- Update the flash BIOS from a file on a diskette
- Verify that the upgrade BIOS matches the target system to prevent accidentally installing an incompatible BIOS
- BIOS boot block update

BIOS upgrades and the Intel Flash Memory Update Utility are available from Intel through the Intel World Wide Web site.

NOTE

Please review the instructions distributed with the upgrade utility before attempting a BIOS upgrade.

For information about	Refer to
Intel's World Wide Web site	Section 1.2, page 16

3.5.1 Language Support

The BIOS Setup program and help messages can be supported in 32 languages. Five languages are available in the BIOS: American English, German, Italian, French, and Spanish. The default language is American English, which is present unless another language is selected in BIOS Setup.

The BIOS includes extensions to support the Kanji character set and other non-ASCII character sets. Translations of other languages may become available at a later date.

3.5.2 Custom Splash Screen

During POST, an Intel splash screen is displayed by default. This splash screen can be replaced with a custom splash screen. A utility is available from Intel to assist with creating a custom splash screen. The custom splash screen can be programmed into the flash memory using the BIOS upgrade utility. Information about this capability is available on the Intel Support World Wide Web site. See Section 1.2 for more information about this site.

3.6 Recovering BIOS Data

Some types of failure can destroy the BIOS. For example, the data can be lost if a power outage occurs while the BIOS is being updated in flash memory. The BIOS can be recovered from a diskette using the BIOS recovery mode. When recovering the BIOS, be aware of the following:

- Recovery requires the use of bootable media in a bootable device.
- Because of the small amount of code available in the nonerasable boot block area, there is no video support. The procedure can be monitored only by listening to the speaker and looking at the diskette drive LED.
- The recovery process may take several minutes; larger BIOS flash memory devices require more time.
- A single beep indicates the beginning of the BIOS recovery process.
- Two beeps and the end of activity in the diskette drive indicate successful BIOS recovery.
- A series of continuous beeps indicates a failed BIOS recovery.

To create a BIOS recovery diskette, a bootable diskette must be created and the BIOS update files copied to it. BIOS upgrades and the Intel Flash Memory Update utility are available from Intel Customer Support through the Intel World Wide Web site.

NOTE

If the computer is configured to boot from an LS-120 diskette (in the Setup program's Boot menu), the BIOS recovery diskette must be a standard 1.44 MB diskette, not a 120 MB diskette.

For information about	Refer to
The BIOS recovery mode jumper settings	Table 47, page 64
The Boot menu in the BIOS Setup program	Section 4.7, page 99
Contacting Intel customer support	Section 1.2, page 16

3.7 Boot Options

In the Setup program, the user can choose to boot from a diskette drive, hard drives, CD-ROM, or the network. Boot devices are listed in priority order.

For information about	Refer to
The default boot order	Table 73, page 99

3.7.1 CD-ROM and Network Boot

Booting from CD-ROM is supported in compliance with the El Torito bootable CD-ROM format specification. The network can also be selected as a boot device. This selection allows booting from a network add-in card with a remote boot ROM installed.

For information about	Refer to
The El Torito specification	Section 1.3, page 16

3.7.2 Booting Without Attached Devices

For use in embedded applications, the BIOS has been designed so that after passing the POST, the operating system loader is invoked even if the keyboard and mouse are not attached.

3.7.3 Default Settings After Battery and Power Failure

If the battery and AC power fail, standard defaults, not custom defaults, will be loaded into CMOS RAM at power on.

3.8 USB Legacy Support

USB legacy support enables a USB devices such as keyboards and mice to be used when no operating system USB drivers are in place. USB legacy support is used only in accessing the BIOS Setup program and installing an operating system that supports USB. By default, USB legacy support is set to Auto. The Auto setting enables USB legacy support if a supported USB device is connected to the USB port.

This sequence describes how USB legacy support operates in the Auto (default) mode.

1. When you power up the computer, USB legacy support is disabled.
2. POST begins.
3. USB legacy support is temporarily enabled by the BIOS. This allows you to use a USB keyboard to enter the BIOS Setup program or the maintenance mode.
4. POST completes and disables USB legacy support (unless it was set to Enabled or Auto while in the BIOS Setup program).
5. The operating system loads. While the operating system is loading, USB keyboards and mice are not recognized (unless USB legacy support was set to Enabled or Auto while in the BIOS Setup program). After the operating system loads the USB drivers, the USB devices are recognized by the operating system.

To install an operating system that supports USB, enable USB Legacy support or set it to Auto in the BIOS Setup program and follow the operating system's installation instructions. Once the operating system is installed and the USB drivers have been configured, USB legacy support is no longer used. USB Legacy support can be left enabled or set to Auto in the BIOS Setup program if needed.

Notes on using USB legacy support:

- Do not use USB devices with an operating system that does not support USB. USB legacy is not intended to support the use of USB devices in a non-USB aware operating system.
- USB legacy support is for keyboards and mice only. Other USB devices are not supported.

3.9 BIOS Security Features

The BIOS includes security features that restrict access to the BIOS Setup program and restrict who can boot the computer. A supervisor password and a user password can be set for accessing the Setup program and for booting the computer, with the following restrictions:

- The supervisor password gives unrestricted access to view and change all the Setup options in the Setup program. This is supervisor mode.
- The user password gives restricted access to view and change Setup options in the Setup program. This is user mode.
- If only the supervisor password is set, pressing the <Enter> key at the password prompt of the Setup program allows the user restricted access to Setup.
- If both the supervisor and user passwords are set, users can enter either the supervisor password or the user password to access Setup. Users have access to Setup respective to which password is entered.
- Setting the user password restricts who can boot the computer. The password prompt will be displayed before the computer is booted. If only the supervisor password is set, the computer boots without asking for a password. If both passwords are set, the user can enter either password to boot the computer.

Table 56 shows the effects of setting the supervisor password and user password. This table is for reference only and is not displayed on the screen.

Table 56. Supervisor and User Password Functions

Password Set	Supervisor Mode	User Mode	Setup Options	Password to Enter Setup	Password During Boot
Neither	Can change all options *	Can change all options *	None	None	None
Supervisor only	Can change all options	Can change a limited number of options	Supervisor Password	Supervisor	None
User only	N/A	Can change all options	Enter Password Clear User Password	User	User
Supervisor and user set	Can change all options	Can change a limited number of options	Supervisor Password Enter Password	Supervisor or user	Supervisor or user

* If no password is set, any user can change all Setup options.

For information about	Refer to
Setting user and supervisor passwords	Section 4.5, page 97

4 BIOS Setup Program

What This Chapter Contains

4.1 Introduction

The Setup program is used for viewing and changing the BIOS settings for a computer. The user accesses Setup by pressing the <F2> key after the Power-On Self Test (POST) memory test begins and before the operating system boot begins. The menu bar is shown below.

```
Maintenance  Main      Advanced  Security  Power     Boot      Exit
```

Table 57 lists the BIOS Setup program menu functions.

Table 57. Setup Menu Bar

Maintenance	Main	Advanced	Security	Power	Boot	Exit
Clears passwords and enables extended configuration mode	Allocates resources for hardware components	Configures advanced features available through the chipset	Sets passwords and security features	Configures power management features	Selects boot options and power supply controls	Saves or discards changes to Setup program options

NOTE

In this chapter, all examples of the BIOS Setup Program menu bar include the maintenance menu; however, the maintenance menu is displayed only when the board is in configuration mode. Section 2.9.1 on page 64 tells how to put the board in configuration mode.

Table 58 shows the function keys available for menu screens.

Table 58. Setup Function Keys

Setup Key	Description
<←> or <→>	Selects a different menu screen
<↑> or <↓>	Selects an item
<Tab>	Selects a field
<Enter>	Executes command or selects the submenu
<F9>	Loads the default configuration values for the current menu
<F10>	Saves the current values and exits the BIOS Setup program
<Esc>	Exits the menu

4.2 Maintenance Menu

The menu bar is shown below.

Maintenance	Main	Advanced	Security	Power	Boot	Exit

The menu shown in Table 59 is for clearing Setup passwords. Setup only displays this menu in configuration mode. See Section 2.9.1 on page 64 for configuration mode setting information.

Table 59. Maintenance Menu

Feature	Options	Description
Clear All Passwords	No options	Clears the user and supervisor passwords.
Clear BIS Credentials	No options	Clears the Wired for Management Boot Integrity Service (BIS) credentials.
Extended Configuration	No options	Allows user to manually configure advanced memory settings.
Processor Information	No options	
Processor Microcode Update Revision	No options	Displays the revision number of the processor microcode.
Processor Stepping Signature	No options	Displays the processor stepping signature.

4.2.1 Extended Configuration Submenu

The menu bar is shown below.

Maintenance	Main	Advanced	Security	Power	Boot	Exit

Table 60 describes the Extended Configuration menu. This menu allows the user to configure memory settings that are highly technical.

⚠ CAUTION

Choosing the wrong settings could cause system problems. Do not change these settings unless you have all the necessary information about the installed memory.

Table 60. Extended Configuration Menu

Feature	Options	Description
Extended Configuration	• **Default (default)** • User Defined	Enables access to the extended memory configuration options.
SDRAM Auto-Configuration	• **Auto (default)** • User Defined	Sets extended memory configuration options to auto or user defined.
SDRAM CAS# Latency	• 3 • 2 • **Auto (default)**	Selects the number of clock cycles required to address a column in memory.
SDRAM RAS# to CAS# Delay	• 3 • 2 • **Auto (default)**	Selects the number of clock cycles between addressing a row and addressing a column.
SDRAM RAS# Precharge	• 3 • 2 • **Auto (default)**	Selects the length of time required before accessing a new row.

4.3 Main Menu

The menu bar is shown below.

Maintenance	**Main**	Advanced	Security	Power	Boot	Exit

Table 61 describes the Main Menu. This menu reports processor and memory information and is for configuring the system date and system time.

Table 61. Main Menu

Feature	Options	Description
BIOS Version	No options	Displays the version of the BIOS.
Processor Type	No options	Displays processor type.
Processor Speed	No options	Displays processor speed.
Cache RAM	No options	Displays the size of second-level cache.
Total Memory	No options	Displays the total amount of RAM on the board.
Bank 0 Bank 1	No options	Displays the type of DIMM installed in each memory bank.
Processor Serial Number	• Enabled • **Disabled (default)**	Enables and disables the processor serial number (only available with a Pentium III processor installed).
System Time	Hour, minute, and second	Specifies the current time.
System Date	Month, day, and year	Specifies the current date.

4.4 Advanced Menu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

Table 62 describes the Advanced Menu. This menu is used for setting advanced features that are available through the chipset.

Table 62. Advanced Menu

Feature	Options	Description
Extended Configuration	No options	Indicates whether extended configuration settings have been modified from the default setting.
PCI Configuration	No options	Allows access to PCI IRQ mapping.
Boot Configuration	No options	Configures Plug and Play and the Numlock key, and resets configuration data. When selected, displays the Boot Settings Configuration submenu.
Peripheral Configuration	No options	Configures peripheral ports and devices. When selected, displays the Peripheral Configuration submenu.
IDE Configuration	No options	Specifies type of connected IDE device.
Diskette Configuration	No options	When selected, displays the Floppy Options submenu.
Event Log Configuration	No options	Configures Event Logging. When selected, displays the Event Log Configuration submenu.
Video Configuration	No options	Configures video features. When selected, displays the Video Configuration submenu.

4.4.1 PCI Configuration Submenu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 63 is for accessing PCI IRQ mapping.

Table 63. PCI Configuration Submenu

Feature	Options	Description
PCI Slot1 IRQ Priority	• **Auto (default)** • 9 • 10 • 11	Allows the user to map the PCI IRQ for slot 1 to a particular hardware interrupt.
PCI Slot2 IRQ Priority	• **Auto (default)** • 9 • 10 • 11	Allows the user to map the PCI IRQ for slot 2 to a particular hardware interrupt.
PCI Slot3 IRQ Priority	• **Auto (default)** • 9 • 10 • 11	Allows the user to map the PCI IRQ for slot 3 to a particular hardware interrupt.
PCI Slot4 IRQ Priority	• **Auto (default)** • 9 • 10 • 11	Allows the user to map the PCI IRQ for slot 4 to a particular hardware interrupt.

4.4.2 Boot Setting Configuration Submenu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 64 is used for setting Plug and Play and the Numlock key, and for resetting configuration data.

Table 64. Boot Setting Configuration Submenu

Feature	Options	Description
Plug & Play O/S	• **No (default)** • Yes	Specifies if manual configuration is desired. *No* lets the BIOS configure all devices. This setting is appropriate when using a Plug and Play operating system. *Yes* lets the operating system configure Plug and Play devices. This option is available for use during lab testing.
Reset Config Data	• **No (default)** • Yes	Clears the BIOS configuration data on the next boot.
Numlock	Off **On (default)**	Specifies the power on state of the Numlock feature on the numeric keypad of the keyboard.

4.4.3 Peripheral Configuration Submenu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 65 is used for configuring the computer peripherals.

Table 65. Peripheral Configuration Submenu

Feature	Options	Description
Serial port A	• Disabled • Enabled • **Auto (default)**	Configures serial port A. *Auto* assigns the first free COM port, normally COM1, the address 3F8h, and the interrupt IRQ4. An * (asterisk) displayed next to an address indicates a conflict with another device.
Base I/O address	• **3F8 (default)** • 2F8 • 3E8 • 2E8	Specifies the base I/O address for serial port A, if Serial Port A is set to Enabled.
Interrupt	• IRQ 3 • **IRQ 4 (default)**	Specifies the interrupt for serial port A, if Serial Port A is set to Enabled.
Serial port B	• Disabled • Enabled • **Auto (default)**	Configures serial port B. *Auto* assigns the first free COM port, normally COM2, the address 2F8h and the interrupt IRQ3. An * (asterisk) displayed next to an address indicates a conflict with another device. If either serial port address is set, that address will not appear in the list of options for the other serial port.
Mode	• **Normal (default)** • IrDA SIR-A • ASK_IR	Specifies the mode for serial port B for normal (COM 2) or infrared applications. This option is not available if serial port B has been disabled.

continued

Table 65. Peripheral Configuration Submenu (continued)

Feature	Options	Description
Base I/O address	• **2F8 (default)** • 3E8 • 2E8	Specifies the base I/O address for serial port B.
Interrupt	• **IRQ 3 (default)** • IRQ 4	Specifies the interrupt for serial port B.
Parallel port	• Disabled • Enabled • **Auto (default)**	Configures the parallel port. *Auto* assigns LPT1 the address 378h and the interrupt IRQ7. An * (asterisk) displayed next to an address indicates a conflict with another device.
Mode	• Output Only • **Bi-directional (default)** • EPP • ECP	Selects the mode for the parallel port. Not available if the parallel port is disabled. *Output Only* operates in AT-compatible mode. *Bi-directional* operates in PS/2-compatible mode. *EPP* is Extended Parallel Port mode, a high-speed bi-directional mode. *ECP* is Enhanced Capabilities Port mode, a high-speed bi-directional mode.
Base I/O address	• **378 (default)** • 278 • 228	Specifies the base I/O address for the parallel port.
Interrupt	• IRQ 5 • **IRQ 7 (default)**	Specifies the interrupt for the parallel port.
Audio Device	• Disabled • **Enabled (default)**	Enables or disables the onboard audio subsystem.
LAN Device	• Disabled • **Enabled (default)**	Enables or disables the optional onboard 10/100 Ethernet.
Legacy USB Support	• Disabled • Enabled • **Auto (default)**	Enables or disables USB legacy support.

4.4.4 IDE Configuration Submenu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 66 is used to configure IDE device options.

Table 66. IDE Device Configuration

Feature	Options	Description
IDE Controller	• Disabled • Primary • Secondary • **Both (default)**	Specifies the integrated IDE controller. *Primary* enables only the Primary IDE Controller. *Secondary* enables only the Secondary IDE Controller. *Both* enables both IDE controllers.
Hard Disk Pre-Delay	• **Disabled (default)** • 3 Seconds • 6 Seconds • 9 Seconds • 12 Seconds • 15 Seconds • 21 Seconds • 30 Seconds	Specifies the hard disk drive pre-delay.
Primary IDE Master	No options	Reports type of connected IDE device. When selected, displays the Primary IDE Master submenu.
Primary IDE Slave	No options	Reports type of connected IDE device. When selected, displays the Primary IDE Slave submenu.
Secondary IDE Master	No options	Reports type of connected IDE device. When selected, displays the Secondary IDE Master submenu.
Secondary IDE Slave	No options	Reports type of connected IDE device. When selected, displays the Secondary IDE Slave submenu.

4.4.4.1 IDE Configuration Submenus

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration **Primary IDE Master** **Primary IDE Slave** **Secondary IDE Master** **Secondary IDE Slave**
Diskette Configuration
Event Log Configuration
Video Configuration

The submenus represented in Table 67 are used to configure IDE devices.

Table 67. IDE Configuration Submenus

Feature	Options	Description
Type	• None • User • **Auto (default)** • CD-ROM • ATAPI Removable • Other ATAPI • IDE Removable	Specifies the IDE configuration mode for IDE devices. *User* allows the user to change the LBA Mode Control, Multi-Sector Transfers, PIO Mode, and Ultra DMA settings. *Auto* automatically sets the LBA Mode Control, Multi-Sector Transfers, PIO Mode, and Ultra DMA settings.
LBA Mode Control	• Disabled • **Enabled (default)**	Enables or disables the LBA mode control.
Multi-Sector Transfers	• Disabled • 2 Sectors • 4 Sectors • 8 Sectors • **16 Sectors (default)**	Specifies number of sectors per block for transfers from the hard disk drive to memory. Check the hard disk drive's specifications for optimum setting.
PIO Mode	• **Auto (default)** • 0 • 1 • 2 • 3 • 4	Specifies the method for moving data to/from the drive.

continued

Table 67. IDE Configuration Submenus (continued)

Feature	Options	Description
Ultra DMA	• **Disabled (default)** • Mode 0 • Mode 1 • Mode 2 • Mode 3 • Mode 4	Specifies the Ultra DMA mode for the drive.

4.4.5 Diskette Configuration Submenu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 68 is used for configuring the diskette drive.

Table 68. Diskette Configuration Submenu

Feature	Options	Description
Diskette Controller	• Disabled • **Enabled (default)**	Disables or enables the integrated diskette controller.
Floppy A:	• Not Installed • 360 KB, 5¼″ • 1.2 MB, 5¼″ • 720 KB, 3½″ • **1.44/1.25 MB, 3½″ (default)** • 2.88 MB, 3½″	Specifies the capacity and physical size of diskette drive A.
Diskette Write Protect	• **Disabled (default)** • Enabled	Disables or enables write protect for the diskette drive.

4.4.6 Event Log Configuration

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 69 is used for configuring the event logging features.

Table 69. Event Log Configuration Submenu

Feature	Options	Description
Event Log	No options	Indicates if there is space available in the event log.
Event Log Validity	No options	Indicates if the contents of the event log are valid.
View Event Log	No options	Displays the event log.
Clear All Event Logs	• **No (default)** • Yes	Clears the event log after rebooting.
Event Logging	• Disabled • **Enabled (default)**	Enables logging of events.
Mark Events As Read	• **Yes (default)** • No	Marks all events as read.

4.4.7 Video Configuration Submenu

The menu bar is shown below.

Maintenance	Main	**Advanced**	Security	Power	Boot	Exit

Extended Configuration
PCI Configuration
Boot Configuration
Peripheral Configuration
IDE Configuration
Diskette Configuration
Event Log Configuration
Video Configuration

The submenu represented in Table 70 is for configuring video features.

Table 70. Video Configuration Submenu

Feature	Options	Description
Primary Video Adapter	• **AGP (default)** • PCI	Allows the user to select between the onboard direct AGP graphics or the PCI add-in graphics card as primary graphics adapter in a multi-monitor system.

4.5 Security Menu

The menu bar is shown below.

Maintenance	Main	Advanced	**Security**	Power	Boot	Exit

The menu represented in Table 71 is used for setting passwords and security features.

Table 71. Security Menu

Feature	Options	Description
Supervisor Password Is	No options	Reports if there is a supervisor password set.
User Password Is	No options	Reports if there is a user password set.
Set Supervisor Password	Password can be up to seven alphanumeric characters.	Specifies the supervisor password.
Set User Password	Password can be up to seven alphanumeric characters.	Specifies the user password.
Clear User Password	No options	Clears the user password.
User Access Level	• Limited • No Access • View Only • **Full (default)**	Specifies the amount of user access to the Setup program. *Limited* allows only limited fields to be changed. *No Access* prevents user access. *View Only* allows the user to view but not change the fields in the Setup program. *Full* allows any field to be changed except the supervisor password.
Unattended Start	• **Disabled (default)** • Enabled	Disables or enables an unattended start.

4.6 Power Menu

The menu bar is shown below.

Maintenance	Main	Advanced	Security	**Power**	Boot	Exit

The menu represented in Table 72 is used for setting power management features.

Table 72. Power Menu

Feature	Options	Description
Power Management	• Disabled • **Enabled (default)**	Enables or disables the APM BIOS power management feature. (See note below)
Inactivity Timer	• Off • 1 Minute • 5 Minutes • 10 Minutes • **20 Minutes (default)** • 30 Minutes • 60 Minutes • 120 Minutes	Specifies the amount of time before the computer enters standby mode, when APM power management is active. (See note below)
Hard Drive	• Disabled • **Enabled (default)**	Enables or disables power management for hard disks during standby and suspend modes, when APM power management is active. (See note below)
Video Power Down	• Disabled • Standby • **Suspend (default)** • Sleep	Specifies power management for video during standby and suspend modes, when APM power management is active. (See note below)
ACPI Suspend State	• **S1 State (default**) • S3 State	Selects the suspend state the system will use when ACPI power management is active. To enable an instantly available configuration, this must be set to the S3 state and an operating system which fully supports the ACPI S3 suspend state must be installed.

Note: Power Management, Inactivity Timer, Hard Drive, and Video Power Down features apply only for APM operating systems.

4.7 Boot Menu

The menu bar is shown below.

Maintenance	Main	Advanced	Security	Power	**Boot**	Exit

The menu represented in Table 73 is used for setting the boot features and the boot sequence.

Table 73. Boot Menu

Feature	Options	Description
Quiet Boot	• Disabled • **Enabled (default)**	*Disabled* displays normal POST messages. *Enabled* displays the OEM logo instead of POST messages.
Quick Boot	• Disabled • **Enabled (default)**	Enables the computer to boot without running certain POST tests.
Scan User Flash Area	• **Disabled (default)** • Enabled	Enables the BIOS to scan the flash memory for user binary files that are executed at boot time.
After Power Failure	• Stays Off • **Last State (default)** • Power On	Specifies the mode of operation if an AC/Power loss occurs. *Power On* restores power to the computer. *Stay Off* keeps the power off until the power button is pressed. *Last State* restores the previous power state before power loss occurred.
On Modem Ring	• **Stay Off (default)** • Power On	Specifies how the computer responds to an incoming call on an installed modem when the power is off.
On LAN	• Stay Off • **Power On (default)**	Specifies how the computer responds to a LAN wakeup event when the power is off.
On PME	• **Stay Off (default)** • Power On	Specifies how the computer responds to a PME wakeup event when the power is off.
1st Boot Device 2nd Boot Device 3rd Boot Device 4th Boot Device 5th Boot Device	• Floppy • ARMD-FDD (Note 1) • ARMD-HDD (Note 2) • IDE-HDD • ATAPI CD-ROM • Intel UNDI, PXE 2.0 (build 071) (Note 3) • Disabled	Specifies the boot sequence from the available devices. To specify boot sequence: 1. Select the boot device with <↑> or <↓>. 2. Press <Enter> to set the selection as the intended boot device. The operating system assigns a drive letter to each boot device in the order listed. Changing the order of the devices changes the drive lettering. The default settings for the first through fifth boot devices are, respectively: • Floppy • IDE-HDD • ATAPI CD-ROM • Intel UNDI • Disabled

Notes:
1. ARMD-FDD = ATAPI removable device - floppy disk drive
2. ARMD-HDD = ATAPI removable device - hard disk drive
3. UNDI = Universal Network Interface Card (NIC) Driver Interface
   PXE = Pre-boot eXecution Environment

4.8 Exit Menu

The menu bar is shown below.

Maintenance	Main	Advanced	Security	Power	Boot	**Exit**

The menu represented in Table 74 is used for exiting the Setup program, saving changes, and loading and saving defaults.

Table 74. Exit Menu

Feature	Description
Exit Saving Changes	Exits and saves the changes in CMOS SRAM.
Exit Discarding Changes	Exits without saving any changes made in the Setup program.
Load Setup Defaults	Loads the factory default values for all the Setup options.
Load Custom Defaults	Loads the custom defaults for Setup options.
Save Custom Defaults	Saves the current values as custom defaults. Normally, the BIOS reads the Setup values from flash memory. If this memory is corrupted, the BIOS reads the custom defaults. If no custom defaults are set, the BIOS reads the factory defaults.
Discard Changes	Discards changes without exiting the Setup program. The option values present when the computer was turned on are used.

5 Error Messages and Beep Codes

What This Chapter Contains

5.1 BIOS Error Messages

Table 75 lists the error messages and provides a brief description of each.

Table 75. BIOS Error Messages

Error Message	Explanation
GA20 Error	An error occurred with Gate-A20 when switching to protected mode during the memory test.
Pri Master HDD Error Pri Slave HDD Error Sec Master HDD Error Sec Slave HDD Error	Could not read sector from corresponding drive.
Pri Master Drive – ATAPI Incompatible Pri Slave Drive – ATAPI Incompatible Sec Master Drive – ATAPI Incompatible Sec Slave Drive – ATAPI Incompatible	Corresponding drive is not an ATAPI device. Run Setup to make sure device is selected correctly.
A: Drive Error	No response from diskette drive.
Cache Memory Error	An error occurred while testing L2 cache. Cache memory may be bad.
CMOS Battery Low	The battery may be losing power. Replace the battery soon.
CMOS Display Type Wrong	The display type is different than what has been stored in CMOS. Check Setup to make sure type is correct.
CMOS Checksum Bad	The CMOS checksum is incorrect. CMOS memory may have been corrupted. Run Setup to reset values.
CMOS Settings Wrong	CMOS values are not the same as the last boot. These values have either been corrupted or the battery has failed.
CMOS Date/Time Not Set	The time and/or date values stored in CMOS are invalid. Run Setup to set correct values.
DMA Error	Error during read/write test of DMA controller.
FDC Failure	Error while trying to access diskette drive controller.
HDC Failure	Error while trying to access hard disk controller.
Update Failed	NVRAM was invalid but was unable to be updated.

continued

Table 75. BIOS Error Messages (continued)

Error Message	Explanation
Unlock Keyboard	The system keyboard lock is engaged. The system must be unlocked to continue to boot.
Keyboard Error	Error in the keyboard connection. Make sure keyboard is connected properly.
KB/Interface Error	Keyboard Interface Test failed.
Timer Error	Timer Test failed.
Memory Size Changed	Memory size has changed since the last boot. If no memory was added or removed, then memory may be bad.
Serial presence detect (SPD) device data missing or inconclusive. Do you wish to boot at 100 MHz bus speed? [Y/N]	System memory does not appear to be SPD memory.
No Boot Device Available	System did not find a boot device.
Off Board Parity Error	A parity error occurred on an offboard card. This error is followed by an address.
On Board Parity Error	A parity error occurred in onboard memory. This error is followed by an address.
Parity Error	A parity error occurred in onboard memory at an unknown address.
NVRAM / CMOS / PASSWORD cleared by Jumper	NVRAM, CMOS, and passwords have been cleared. The system should be powered down and the jumper removed.
<CTRL_N> Pressed	CMOS is ignored and NVRAM is cleared. User must enter Setup.

5.2 Port 80h POST Codes

During the POST, the BIOS generates diagnostic progress codes (POST codes) to I/O port 80h. If the POST fails, execution stops and the last POST code generated is left at port 80h. This code is useful for determining the point where an error occurred.

Displaying the POST codes requires an add-in card (often called a POST card). The POST card can decode the port and display the contents on a medium such as a seven-segment display. These cards can be purchased from JDR Microdevices or other sources.

The tables below offer descriptions of the POST codes generated by the BIOS. Table 76 defines the Uncompressed INIT Code Checkpoints, Table 77 describes the Boot Block Recovery Code Checkpoints, and Table 78 lists the Runtime Code Uncompressed in F000 Shadow RAM. Some codes are repeated in the tables because that code applies to more than one operation.

Table 76. Uncompressed INIT Code Checkpoints

Code	Description of POST Operation
D0	NMI is disabled. Onboard keyboard controller and real time clock enabled (if present). Initialization code checksum verification starting.
D1	Keyboard controller BAT test, CPU ID saved, and going to 4GB flat mode.
D3	Initialize chipset, start memory refresh, and determine memory size.
D4	Verify base memory.
D5	Initialization code to be copied to segment 0 and control to be transferred to segment 0.
D6	Control is in segment 0. Used to check if in recovery mode and to verify main BIOS checksum. If in recovery mode or if main BIOS checksum is wrong, go to check point E0 for recovery. Otherwise, go to check point D7 to give control to main BIOS.
D7	Find main BIOS module in ROM image.
D8	Uncompress the main BIOS module.
D9	Copy main BIOS image to F000 shadow RAM and give control to main BIOS in F000 shadow RAM.

Table 77. Boot Block Recovery Code Checkpoints

Code	Description of POST Operation
E0	Onboard diskette controller (if any) is initialized. Compressed recovery code is uncompressed at F000:0000 in shadow RAM. Give control to recovery code at F000 in shadow RAM. Initialize interrupt vector tables, system timer, DMA controller, and interrupt controller.
E8	Initialize extra (Intel recovery) module.
E9	Initialize diskette drive.
EA	Try to boot from diskette. If reading of boot sector is successful, give control to boot sector code.
EB	Boot from diskette failed; look for ATAPI (LS-120, Zip) devices.
EC	Try to boot from ATAPI device. If reading of boot sector is successful, give control to boot sector code.
EF	Boot from diskette and ATAPI device failed. Give two beeps. Retry the booting procedure (go to check point E9).

Table 78. Runtime Code Uncompressed in F000 Shadow RAM

Code	Description of POST Operation
03	NMI is Disabled. Check soft reset/power-on.
05	BIOS stack set. Disable cache if any.
06	Uncompress POST code.
07	Initialize processor and initialize processor data area.
08	Next, calculate CMOS checksum.
0B	Next, do any initialization before executing keyboard BAT.
0C	Keyboard controller I/B free. Issue the BAT command to keyboard controller.
0E	Any initialization after keyboard controller BAT to be done next.
0F	Write keyboard command byte.
10	Issue pin 23, 24 blocking/unblocking command.
11	Check whether <INS>, <END> keys were pressed during power on.
12	Initialize CMOS if "Init CMOS in every boot" is set or if <END> key is pressed. Then disable DMA and interrupt controllers.
13	Video display is disabled and port B is initialized. Chipset initialization about to begin.
14	8254 Timer Test is about to start.
19	Memory Refresh Test is about to start.
1A	Memory Refresh line is toggling. Check 15 µs ON/OFF time.
23	Read 8042 input port and disable Megakey GreenPC feature. Make BIOS code segment writeable.
24	Do any setup before interrupt vector initialization.
25	Interrupt vector initialization to begin. Clear password if necessary.
27	Next, do any initialization before setting video mode.
28	Set monochrome mode and color mode.
2A	Start initialization of different buses, if present (system, static, output devices). (See Section 5.3 for details of different buses.)
2B	Give control for any setup required before optional video ROM check.
2C	Look for optional video ROM and give control.
2D	Give control to do any processing after video ROM returns control.
2E	If EGA/VGA not found, then execute Display Memory R/W Test.
2F	EGA/VGA not found. Display Memory R/W Test about to begin.
30	Display Memory R/W Test passed. Look for the retrace checking.
31	Display Memory R/W Test or retrace checking failed. Do Alternate Display Memory R/W Test.
32	Alternate Display Memory R/W Test passed. Look for the alternate display retrace checking.
34	Video display checking complete. Next, set display mode.
37	Display mode set. Then display the power-on message.
38	Start initialization of different buses, if present (input, IPL, general devices). (See Section 5.3 for details of different buses.)
39	Display different buses initialization error messages. (See Section 5.3 for details of different buses.)
3A	New cursor position read and saved. Ready to display the Hit <DEL> message.

continued

Table 78. Runtime Code Uncompressed in F000 Shadow RAM (continued)

Code	Description of POST Operation
40	Prepare the descriptor tables.
42	Enter virtual mode for memory test.
43	Enable interrupts for diagnostics mode.
44	Initialize data to check memory wrap-around at 0:0.
45	Data initialized. Check for memory wrap-around at 0:0, and find the total system memory size.
46	Memory wrap-around test done. Memory size calculation complete. Ready to write patterns to test memory.
47	Pattern to be tested written in extended memory. Next, write patterns in base 640 K memory.
48	Patterns written in base memory. Find amount of memory below 1 M.
49	Amount of memory below 1 M found and verified. Find out amount of memory above 1 M.
4B	Amount of memory above 1 M found and verified. Check for soft reset and clear memory below 1 M for soft reset. (If power on, go to check point 4Eh).
4C	Memory below 1 M cleared. (Soft reset) Clear memory above 1 M.
4D	Memory above 1 M cleared. (Soft reset) Save the memory size. (Go to checkpoint 52h).
4E	Memory test started. (Not Soft Reset) Ready to display the first 64 K memory size.
4F	Memory size display started. This will be updated during memory test. Run sequential and random memory test.
50	Memory testing/initialization below 1M complete. Ready to adjust displayed memory size for relocation/shadow.
51	Memory size display adjusted due to relocation/shadow. Memory test above 1 M to follow.
52	Memory testing/initialization above 1 M complete. Ready to save memory size information.
53	Memory size information is saved. Processor registers are saved. Ready to enter real mode.
54	Shutdown successful, processor in real mode. Ready to disable gate A20 line and disable parity/NMI.
57	Successfully disabled A20 address line and parity/NMI. Ready to adjust memory size depending on relocation/shadow.
58	Memory size adjusted for relocation/shadow. Ready to clear Hit <DEL> message.
59	Hit <DEL> message cleared. <WAIT...> message displayed. Ready to start DMA and Interrupt Controller Test.
60	DMA Page Register Test passed. Ready to start DMA#1 Base Register Test.
62	DMA#1 Base Register Test passed. Ready to start DMA#2 Base Register Test.
65	DMA#2 Base Register Test passed. Ready to program DMA unit 1 and 2.
66	DMA unit 1 and 2 programming complete. Ready to initialize 8259 interrupt controller.
7F	Extended NMI sources enabling is in progress.
80	Keyboard test started. Clearing output buffer, checking for stuck key. Next, issue keyboard reset command.
81	Keyboard reset error/stuck key found. Ready to issue keyboard controller interface test command.
82	Keyboard controller interface test complete. Ready to write command byte and initialize circular buffer.
83	Command byte written, global data initialization complete. Check for lock-key.

continued

Table 78. Runtime Code Uncompressed in F000 Shadow RAM (continued)

Code	Description of POST Operation
84	Lock-key checking complete. Next, check for memory size mismatch with CMOS.
85	Memory size check complete. Next, display soft error and check for password or bypass Setup.
86	Password checked. Ready to do programming before Setup.
87	Programming before Setup complete. Uncompress Setup code and execute.
88	Returned from CMOS Setup program and cleared screen. Ready to do programming after Setup.
89	Programming after Setup complete. Display power-on message.
8B	First screen message displayed. <WAIT...> message displayed. PS/2 mouse check and extended BIOS data area allocation to be done.
8C	Ready to start Setup options programming.
8D	Ready to reset hard disk controller.
8F	Hard disk controller reset complete. Floppy setup to be done next.
91	Floppy setup complete. Hard disk setup to be done next.
95	Start initialization of different buses optional ROMs from C800. (See Section 5.3 for details of different buses.)
96	Ready to do any init before C800 optional ROM control.
97	Any initialization before C800 optional ROM control is complete. Next, do optional ROM check and control.
98	Optional ROM control is complete. Next, give control to do any required processing after optional ROM returns control and enable external cache.
99	Do any initialization required after optional ROM Test is over. Ready to set up timer data area and printer base address.
9A	Return after setting timer and printer base address. Ready to set the RS-232 base address.
9B	Returned after RS-232 base address. Ready to do any initialization before coprocessor test.
9C	Required initialization before coprocessor test is complete. Ready to initialize coprocessor next.
9D	Coprocessor initialized. Ready to do any initialization after Coprocessor Test.
9E	Initialization after Coprocessor Test is complete. Ready to check extended keyboard, keyboard ID, and NumLock.
A2	Ready to display any soft errors.
A3	Soft error display complete. Ready to set keyboard typematic rate.
A4	Keyboard typematic rate set. Ready to program memory wait states.
A5	Ready to enable parity/NMI.
A7	NMI and parity enabled. Ready to do any initialization required before giving control to optional ROM at E000.
A8	Initialization before E000 ROM control complete. E000 ROM to get control next.
A9	Returned from E000 ROM control. Ready to do any initialization required after E000 optional ROM control.
AA	Initialization after E000 optional ROM control complete. Ready to display the system configuration.
AB	Put INT13 module runtime image to shadow RAM.
AC	Generate MP for multiprocessor support, if present.

continued

Table 78. Runtime Code Uncompressed in F000 Shadow RAM (continued)

Code	Description of POST Operation
AD	Put CGA INT10 module, if present, in shadow RAM.
AE	Uncompress SMBIOS module, initialize SMBIOS code, and form the runtime SMBIOS image in shadow RAM.
B1	Ready to copy any code to specific area.
00	Copying of code to specific area complete. Ready to give control to INT19 boot loader.

5.3 Bus Initialization Checkpoints

The system BIOS gives control to the different buses at the following checkpoints to do various tasks. Table 79 describes the bus initialization checkpoints.

Table 79. Bus Initialization Checkpoints

Checkpoint	Description
2A	Different buses init (system, static, output devices) to start, if present.
38	Different buses init (input, IPL, general devices) to start, if present.
39	Display different buses initialization error messages.
95	Initialization of different buses optional ROMs from C800 to start.

While control is inside the different bus routines, additional checkpoints are output to port 80h as word values to identify the routines under execution. In these word-value checkpoints, the low byte of the checkpoint is the system BIOS checkpoint from which the control is passed to the different bus routines. The high byte of the checkpoint is the indication of which routine is being executed in the different buses. Table 80 describes the upper nibble of the high byte and indicates the function being executed.

Table 80. Upper Nibble High Byte Functions

Value	Description
0	func#0, disable all devices on this bus
1	func#1, initialize static devices on this bus
2	func#2, initialize output device on this bus
3	func#3, initialize input device on this bus
4	func#4, initialize IPL device on this bus
5	func#5, initialize general device on this bus
6	func#6, report errors on this bus
7	func#7, initialize add-on ROM on all buses

Table 81 describes the lower nibble of the high byte and indicates the bus on which the routines are being executed.

Table 81. Lower Nibble High Byte Functions

Value	Description
0	Generic DIM (Device Initialization Manager)
1	Onboard system devices
2	ISA devices
3	EISA devices
4	ISA PnP devices
5	PCI devices

5.4 Speaker

A 47 Ω inductive speaker is mounted on the board. The speaker provides audible error code (beep code) information during the power-on self test (POST).

For information about	Refer to
The location of the onboard speaker	Figure 1, page 14

5.5 BIOS Beep Codes

Whenever a recoverable error occurs during power-on self test (POST), the BIOS displays an error message describing the problem (see Table 82). The BIOS also issues a beep code (one long tone followed by two short tones) during POST if the video configuration fails (a faulty video card or no card installed) or if an external ROM module does not properly checksum to zero.

An external ROM module (for example, a video BIOS) can also issue audible errors, usually consisting of one long tone followed by a series of short tones. For more information on the beep codes issued, check the documentation for that external device.

There are several POST routines that issue a POST terminal error and shut down the system if they fail. Before shutting down the system, the terminal-error handler issues a beep code signifying the test point error, writes the error to I/O port 80h, attempts to initialize the video and writes the error in the upper left corner of the screen (using both monochrome and color adapters).

If POST completes normally, the BIOS issues one short beep before passing control to the operating system.

Table 82. Beep Codes

Beep	Description
1	Refresh failure
2	Parity cannot be reset
3	First 64 KB memory failure
4	Timer not operational
5	Not used
6	8042 GateA20 cannot be toggled
7	Exception interrupt error
8	Display memory R/W error
9	Not used
10	CMOS Shutdown register test error
11	Invalid BIOS (e.g. POST module not found, etc.)